

BOS1921/BOS1931 Piezo Haptic Driver with Digital Front End

1 Features

- High-Voltage Low Power Piezo Driver
 - Drives 100 nF at 190 V_{pk-pk} and 300 Hz while consuming only 350 mW
 - Drives Capacitive Loads up to 820 nF
 - Energy Recovery
 - Differential Output
 - Small Solution Footprint, QFN & WLCSP
- Advanced Piezo Sensing Capabilities (BOS1921 only)
 - 7.6 mV Sensing Resolution
 - Interrupt Generation
 - o Automatic Triggering of Haptic Feedback
- Integrated Digital Front End with I3C/I²C
 - 1024 sample Internal FIFO Interface
 - 1.8 V to 5.0 V Digital I/O Supply
 - Waveform Synthesizer (WFS)
 - Supports Continuous Waveforms Playback
 - State Retention in SLEEP Mode
- Fast Start Up Time of Less Than 300 μs
- Multi-Actuator Synchronization
- Wide Supply Voltage Range of 3 V to 5.5 V

2 Applications

- Mobile Phones and Tablets
- Portable Computers, Keyboards and Mice
- Gaming Controllers, Wearables
- Electronic Cooling
- Micropump

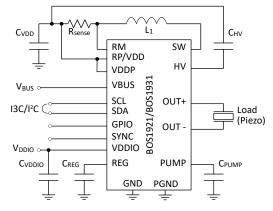


Figure 1: Simplified schematic

3 Description

The BOS1921 (driving + sensing) and BOS1931 (driving) are a single-chip piezo actuator driver with energy recovery, based on Boreas' patented CapDrive™ technology. It can drive actuators with waveforms up to 190 V_{pk-pk} while operating from a 3 to 5.5 V supply voltage. Its low power and small size make it ideal for a variety of applications requiring minimal power consumption.

The BOS1921 features high-resolution piezo sensing capabilities, allowing haptic feedback to be automatically played when detection conditions are met.

The BOS1921/BOS1931 differential driver achieves low distortion waveforms and quiet actuator operation. All settings are adjustable through the digital front end to reduce the BOM.

Data and configuration parameters are easily communicated to the BOS1921/BOS1931 through its two-wire MIPI I3C interface. The MIPI I3C is also backward compatible with I²C for easy integration in most systems. A flexible deep FIFO enables the streaming of digital waveform data for playback or the transmission of burst data for more bandwidth efficiency. The BOS1921/BOS1931 also integrates a waveform synthesizer and 2 kB of RAM waveform memory to generate HD haptic waveforms with minimal communication bandwidth.

A dedicated SYNC pin can synchronize multiple BOS1921/BOS1931 controllers to simultaneously drive multiple actuators within 2 μ s.

With a typical start-up time of less than 300 μ s, the device latency is negligible in most systems.

Various safety systems protect the BOS1921/BOS1931 from damage in case of a fault.

See section 9 for package dimensions and section 11 for ordering information.



TABLE OF CONTENT

1 FEATURES	1
2 APPLICATIONS	1
3 DESCRIPTION	1
4 PINS & BUMPS CONFIGURATION AND FUNCTIONS	3
5 SPECIFICATIONS	5
5.1 Absolute Maximum Ratings	5
5.2 THERMAL RESISTANCE	
5.3 RECOMMENDED OPERATING CONDITIONS	5
5.4 ELECTRICAL CHARACTERISTICS	
5.5 TIMING CHARACTERISTICS	
5.6 TYPICAL PERFORMANCE CHARACTERISTICS	
6 FUNCTIONAL DESCRIPTION	11
6.1 Overview	
6.2 FEATURES	
6.3 DIGITAL INTERFACE	
6.4 PIEZO ACTUATOR SENSING (BOS1921 ONLY)	
6.5 DIRECT MODE	_
6.6 FIFO MODE	
6.7 RAM PLAYBACK MODE	
6.8 RAM SYNTHESIS MODE	
6.9 WFS COMMAND INTERPRETER	
6.10 REGISTER MAP	
7 IMPLEMENTATION	
7.1 DIFFERENTIAL OUTPUT CONFIGURATION	
7.2 SINGLE-ENDED CONFIGURATION	
7.3 External Components	
7.4 Initialization	
7.5 DESIGN METHODOLOGY: SELECTION OF COMPONENT	
7.6 DESIGN METHODOLOGY: PROGRAMMING	
7.7 Noise Reduction	87
8 PCB LAYOUT EXAMPLE	88
9 MECHANICAL	90
9.1 QFN PACKAGE DESCRIPTION	90
9.2 WLCSP PACKAGE DESCRIPTION	92
9.3 TAPE AND REEL SPECIFICATIONS	95
10 KNOWN ISSUES	96
10.1 Incorrect Activation of Output Bridge Protection	
10.2 TIMEOUT RESETS PLAY_SRATE	96
10.3 WAVEFORM AMPLITUDE DRIFT WITH RELOFF OPTION	
10.4 MINIMUM SLEW-RATE OF VBUS SUPPLY	96
11 ORDERING INFORMATION	97
12 DOCUMENT HISTORY	98
13 NOTICE AND WARNING	99



4 Pins & Bumps Configuration and Functions

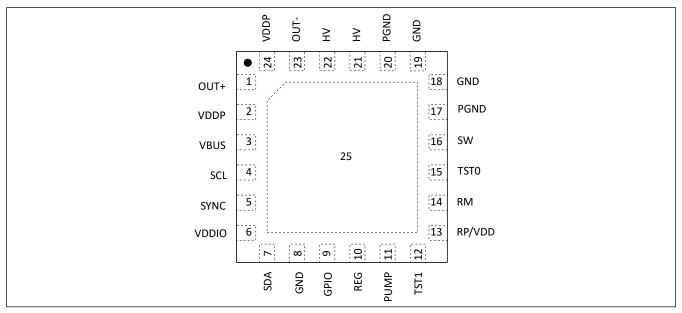


Figure 2: QFN 24L 4.0mm × 4.0mm package with exposed thermal pad (TOP VIEW; NOT TO SCALE)

Table 1: QFN package pins description

PIN NO.	NAME	TYPE	DESCRIPTION	
1	OUT+	Output	Positive Differential Output	
2	VDDP	Power	Intermediate Supply Voltage	
3	VBUS	Power	Main Power Supply	
4	SCL	Input	I3C/I ² C clock	
5	SYNC	Input/Output	Synchronization pin, tie de ground if unused	
6	VDDIO	Power	Digital IO Power Supply	
7	SDA	Input/Output	I3C/I ² C data	
8	GND	Power	Supply Ground	
9	GPIO	Input/Output	General-purpose input output	
10	REG	Power	Internal 1.8 V Regulator Output	
11	PUMP	Power	Internal 5 V Charge Pump Voltage	
12	TST1	-	No connect	
13	RP/VDD	Power	Current Sense Positive Input / Supply Voltage	
14	RM	Input	Current Sense Negative Input	
15	TST0	-	Connect to GND	
16	SW	Power	Internal Power Converter Switch Pin	
17	PGND	Power	Supply Ground of the Power Stage	
18	GND	Power	Supply Ground	
19	GND	Power	Supply Ground	
20	PGND	Power	Supply Ground of the Power Stage	
21	HV	Power	High-Voltage Output	
22	HV	Power	High-Voltage Output	
23	OUT-	Output	Negative Differential Output	
24	VDDP	Power	Intermediate Supply Voltage	
25	GND	Power	Exposed thermal pad is GND and must be soldered to PCB	



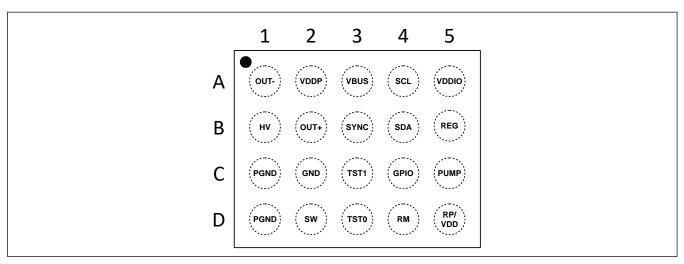


Figure 3: WLCSP 20B 2.1mm × 1.7mm package (TOP VIEW; NOT TO SCALE)

Table 2: WLCSP package bumps description

BUMP NO.	NAME	TYPE	DESCRIPTION
A1	OUT-	Output	Negative Differential Output
A2	VDDP	Power	Intermediate Supply Voltage
A3	VBUS	Power	Main Power Supply
A4	SCL	Input	I3C/I ² C clock
A5	VDDIO	Power	Digital IO Power Supply
B1	HV	Power	High-Voltage Output
B2	OUT+	Output	Positive Differential Output
В3	SYNC	Input/Output	Synchronization pin
B4	SDA	Input/Output	I3C/I ² C data
B5	REG	Power	Internal 1.8 V Regulator Output
C1	PGND	Power	Supply Ground of the Power Stage
C2	GND	Power	Supply Ground
C3	TST1	-	No connect
C4	GPIO	Input/Output	General-purpose input output
C5	PUMP	Power	Internal 5 V Charge Pump Voltage
D1	PGND	Power	Supply Ground of the Power Stage
D2	SW	Power	Internal Power Converter Switch Pin
D3	TST0	-	Connect to GND
D4	RM	Input	Current Sense Negative Input
D5	RP/VDD	Input	Current Sense Positive Input / Supply Voltage



5 Specifications

5.1 Absolute Maximum Ratings

Table 3: Absolute maximum ratings[‡]

	SYMBOL	PARAMETER	MIN	NOM	MAX	UNIT
1		Voltage at pins HV, OUT+, OUT-, SW	-0.3		110	V
2		Voltage at all other pins	-0.3		7	V
3	T _{stg}	Storage temperature	-65		150	°C
4	Tı	Junction Temperature	-40		150	°C
5	SOA	Safe operating area	See Figure 14.		-	

[‡]Exceeding these values may cause permanent damage. Functional operation under these conditions is not guaranteed.

5.2 Thermal Resistance

Table 4: Thermal resistance[‡]

	SYMBOL	PARAMETER	PACKAGE	MIN	NOM (1,2)	MAX	UNIT
1	ӨЈА	Thermal resistance: junction	QFN 24L 4.0mm × 4.0mm		TBD		°C/W
		to ambient	WLCSP 20B 2.1mm × 1.7mm		100		°C/W

[‡]Power dissipated in the package is not obvious to calculate. Please consult Boréas Technologies before using these parameters.

5.3 Recommended Operating Conditions

Table 5: Recommended operating conditions

	SYMBOL	PARAMETER	TEST CONDITIONS	MIN	NOM	MAX	UNIT
1	T _A	Operating Temperature	Operating free-air temperature	-40		85	°C
2	<i>V_{BUS}, V_{DD}</i> ⁽¹⁾	Supply voltage		3.0		5.5	V
3	$V_{DDIO}^{(2)}$	I/O Supply voltage		1.62		5.5	V
4	CL	Load capacitance	V _{OUT} = 190 V _{pk-pk} , f _{OUT} = 300 Hz			100	nF
			V _{OUT} = 100 V _{pk-pk} , f _{OUT} = 220 Hz			470	nF
			V _{OUT} = 100 V _{pk-pk} , f _{OUT} = 130 Hz			820	nF
5	L ₁	Inductance		10		68	μН
6	Rsense	Sense resistor		0.2		1.0	Ω
7	fоuт	Output frequency	<u>PLAY MODE[1:0]</u> = 0x3	3.9		1000	Hz
8	Isw	Transient current at SW pin				1.3	Α

⁽¹⁾ If the Unidirectional Power Input mode is enabled (\underline{UPI} bit set to 0x1), V_{DD} may increase above the maximum recommended operating condition, see section 6.2.13.

⁽²⁾ Digital I/O voltage (V_{DDIO}) must match the communication interface voltage.



5.4 Electrical Characteristics

Table 6: Electrical characteristics. Conditions: $T_A = 25$ °C, $V_{BUS} = 3.6$ V (unless otherwise noted)

	SYMBOL	PARAMETER	TEST CONDITIONS	MIN	NOM	MAX	UNIT
1	V_{REG}	Voltage at REG pin		1.75	1.80	1.85	٧
2	VIL	Digital low-level input voltage	SDA, SCL, GPIO & SYNC pins			0.5	٧
3	V _{IH}	Digital high-level input voltage		V _{DDIO} ×0.7		V _{DDIO} +0.3	V
4	VoL	Digital low-level output voltage				0.4	V
5	V _{OH}	Digital high-level output voltage		V _{DDIO} ×0.8			
6	V _{OUT(FS)}	Full-scale output voltage		186	190	194	V _{pk-pk}
7	I _{Q_VBUS}	V _{BUS} Quiescent current	SLEEP State ⁽¹⁾⁽²⁾ <u>OE</u> =0x0, <u>DS</u> =0x1, <u>RET</u> =0x1		0.6	10	μΑ
			SLEEP State OE=0x0, DS=0x1, RET=0x0		2.4		μΑ
			IDLE State OE=0x0, DS=0x0		530		μΑ
8	I _{BUS,AVG}	Average V _{BUS} supply current	SENSING=0x1 ⁽³⁾		1.9		mA
		during operation & OE=0x1	F _{OUT} = DC V _{OUT} = 95 V C _{Load} = 100 nF		3.7		mA
			$f_{OUT} = 300 \text{ Hz}$ $V_{OUT} = 190 \text{ V}_{pk-pk}$ $C_{Load} = 100 \text{ nF}$		90		mA
			f _{OUT} = 200 Hz V _{OUT} = 190 Vpk-pk C _L = 10 nF <u>CCM</u> = 0x0		14.5		mA
9	THD+N	Total Harmonic Distortion + Noise ⁽²⁾	$ f_{OUT} = 300 \text{ Hz} $ $V_{OUT} = 190 \text{ V}_{pk-pk} $ $C_{Load} = 100 \text{ nF} $		0.3	1	%
10	f _{s-FIFO}	Programmable FIFO playback rate	PLAY_SRATE[2:0]=0x0 PLAY_SRATE[2:0]=0x7	1008 7.875	1024 8	1040 8.125	ksps
11	PSR ⁽³⁾	Piezo Sensing Resolution	CONFIG.GAINS=0x1		7.6		mV
12	t _{start} (2)	Start-up Time	Time from SLEEP mode to haptic waveform playback			300	μs
13	DHL ⁽²⁾⁽³⁾	Sensing Detection to Haptic Feedback Latency	Time from sensing detection event to automatic playback			30	μs

⁽¹⁾ The VDDIO supply should be powered off when state retention is disabled (\underbrace{RET} bit set to 0x1) to minimize the total quiescent current of the device.

⁽²⁾ Validated by design.

⁽³⁾ BOS1921 only.



5.5 Timing Characteristics

5.5.1 I²C

Table 7: Timing characteristics. Condition: I^2C communication mode, $T_A = 25$ °C, $V_{DDIO} = 1.8$ V, SDA/SCL load = 50 pF

			FAST MODE		FAST MODE +		
	SYMBOL	PARAMETER	MIN	MAX	MIN	MAX	UNIT
1	f _{SCL}	SCL clock frequency ⁽¹⁾	0	0.4	0	1.0	MHz
2	t _{LOW}	SCL low period	1300		500		ns
3	t _{HIGH}	SCL high period	600		260		ns
4	t _R	SDA/SCL rise time ⁽¹⁾	20	300	-	120	ns
5	tғ	SDA/SCL fall time ⁽¹⁾	-	300	-	120	ns
6	t _{SU_DAT}	Data setup time ⁽¹⁾	100		50		ns
7	thd_dat	Data hold time ⁽¹⁾	0	-	0	-	ns
8	tsu_sta	Setup time for a repeated START condition ⁽¹⁾	600		260		ns
9	t _{HD_STA}	Hold time for a (repeated) START condition ⁽¹⁾	600		260		ns
10	t _{SU_STO}	Setup time for STOP condition ⁽¹⁾	600		260		ns
11	t BUF	Bus free time (time between the STOP and START conditions) (1)	1300		500		ns
12	t _{SPIKE}	Spike suppression pulse width ⁽¹⁾	0	50	0	50	ns

(1) Validated by design.

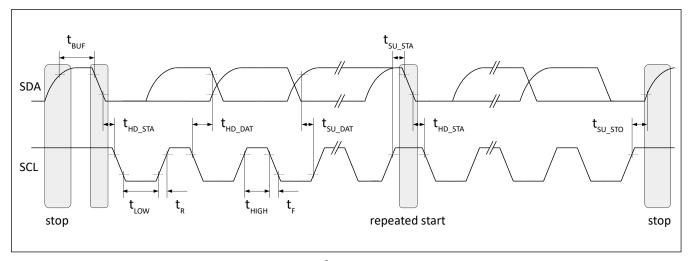


Figure 4: I²C timing diagram



5.5.2 I3C

Table 8: Timing characteristics. Condition: I3C push-pull, T_A = 25°C, V_{DDIO} = 1.8 V, SDA/SCL load = 50 pF

	SYMBOL	PARAMETER	MIN	MAX	UNIT
1	f _{SCL}	SCL clock frequency (1)	0.01	12.5	MHz
2	t _{LOW}	SCL low period	24		ns
3	t _{нібн}	SCL high period	24	41 (2)	ns
4	t _{CR}	SCL rise time ⁽¹⁾		The minimum between whether 150×106/f _{SCL} or 60	ns
7	t CF	SCL fall time (1)		The minimum between whether 150×106/f _{scl} or 60	ns
8	tsu	Data setup time	3		ns
9	t _{HD} (controller)	Data hold time	tCR +3, tCF +3		ns
10	t _{HD (target)}	Data hold time	0		ns
11	t _{CBSr}	Clock before repeated START condition (1)	19.2		ns
12	tcas	Clock after START condition (1)	38.4		ns
13	tcasr	Clock after repeated START condition (1)	38.4		ns
14	t _{CBP}	Clock before STOP condition (1)	19.2		ns
15	t _{AVAL}	Bus available ⁽¹⁾	1		μs

⁽¹⁾ Validated by design.

⁽²⁾ This maximum high period may be exceeded when the signals can be safely seen by legacy I^2C devices.

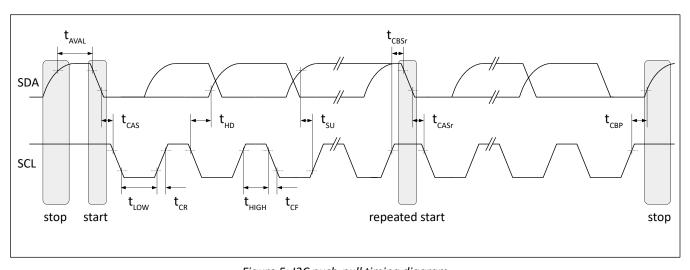
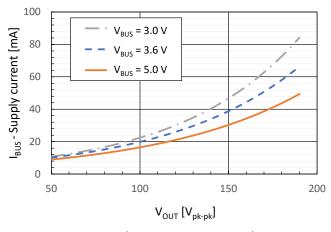


Figure 5: I3C push-pull timing diagram



5.6 Typical Performance Characteristics

Typical performance characteristics for the following conditions: $T_A = 25$ °C, $V_{BUS} = 3.6$ V, $C_L = 100$ nF, $V_{OUT} = 190$ V_{pk-pk} and $f_{OUT} = 200$ Hz (unless otherwise noted).



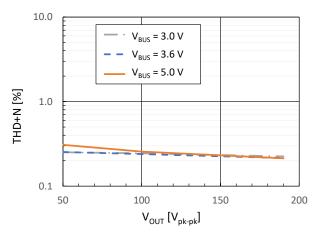
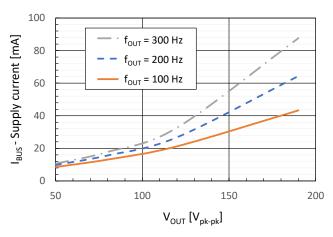


Figure 6: Supply Current vs Output Voltage

Figure 7: Total Harmonic Distortion + Noise vs Output Voltage



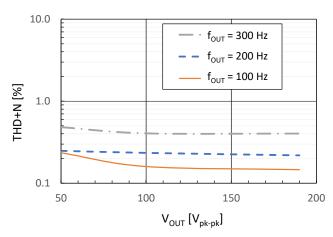
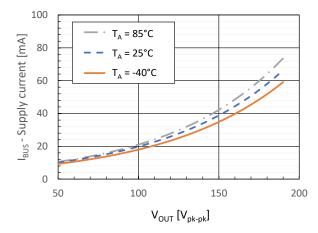


Figure 8: Supply Current vs Output Voltage

Figure 9: Total Harmonic Distortion + Noise vs Output Voltage



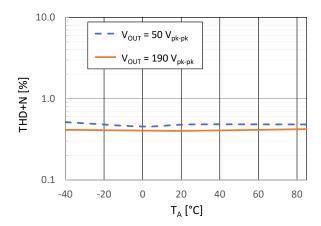
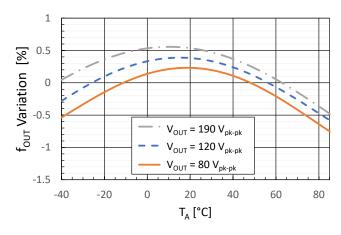


Figure 10: Supply Current vs Operating free-air Temperature

Figure 11: Total Harmonic Distortion + Noise vs Operating free-air Temperature





600 V_{BUS} = 5.0 V V_{BUS} = 3.6 V V_{BUS} = 3.6 V -40 -20 0 20 40 60 80 T_A [°C]

Figure 12: Output Frequency Variation vs Operating free-air Temperature

Figure 13: Supply Quiescent Current in IDLE Mode vs Operating free-air Temperature

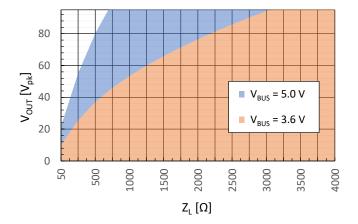


Figure 14: Safe Operating Area at Isw max



6 Functional Description

6.1 Overview

The BOS1921/BOS1931 is a highly integrated low-power piezo actuator driver with an integrated digital front end and energy recovery, based on Boreas's patented CapDriveTM technology. The device requires a single low-voltage supply and 7 passive components to generate waveforms of up to 190 V_{pk-pk} .

The digital interface enables the transmission of the digital waveform data from any MCU with an I3C or I^2C interface to the BOS1921/BOS1931. A flexible FIFO interface enables the generation of haptic playback by streaming the digital waveform data or transmitting the digital waveform data in groups for more bandwidth efficiency. Waveforms can be generated by reading data from the FIFO at various sampling rates.

The BOS1921/BOS1931 integrates a Waveform Synthesizer (WFS) and a 2 kB on-chip 1024×16 RAM that enable haptic waveform generation using RAM Playback mode and RAM Synthesis mode. The WFS allows the generation of customized continuous haptic waveforms with minimal intervention by the host MCU.

The BOS1921 features an advanced sensing interface that allows mechanical buttons to be replaced with an enhanced user interface. Piezo actuator press/release trigger conditions allow the detection of an interaction with a piezo actuator and automatically trigger haptic waveform feedback within 30 μ s. A GPIO pin can be used as an interrupt to indicate the MCU that a sensing voltage event has occurred or a change in the device state.

The BOS1921/BOS1931 can use any commercial off-the-shelf (COTS) inductor. The inductor value can be chosen to optimize the power, size or performance depending on the user's application. With a start-up time of less than 300 μ s from its low-power mode, the device can be used in applications requiring low latency.

6.2 Features

6.2.1 Digital Front-End Interface

The BOS1921/BOS1931 uses an I3C target interface supporting SDR communication up to 12.5 Mbps. This high-speed communication interface enables multiple ICs to share a common communication bus. Its digital front-end enables waveform data to be stored in memory. The digital interface also provides access to internal registers which control the BOS1921/BOS1931 operation and performance, see section 6.3 for more details.

6.2.2 GPIO

A General-Purpose Input / Output (GPIO) pin in the VDDIO domain is available and supports an open-drain (default) or push-pull configuration. The GPIO is active-low and can be used as an interrupt to notify the host MCU of various events such as sense voltage events or an error. The GPIO can also be used as an input to trigger a predefined haptic waveform output.

The GPIO pin can be configured with the following register bits:

- COMM.GPIODIR is used to set the GPIO pin as input or output.
- COMM.GPIOSEL[2:0] is used to select the signal that is output to the GPIO pin.
- COMM.OD is used to set the GPIO pin to push-pull or open-drain configuration.



6.2.3 Flexible Waveform Generation

The output waveform voltage range can be selected between ±95 V and ±13.25 V as detailed in Table 9.

Table 9: Output Voltage Ranges List

REGISTER	REGISTER VALUE	OUTPUT RANGE (V)	OUTPUT RESOLUTION (V)
CONFIG.GAIND	0x1	±13.25	0.0076
CONFIG.GAIND	0x0	±95	0.0545

6.2.3.1 Direct Mode

With <u>PLAY MODE[1:0]</u> bits set to 0x0, the haptic waveform samples are played as they are sent from the host MCU to the RAM using <u>REFERENCE</u> register. The rate at which the RAM data is read to generate the haptic waveform is set by <u>PLAY SRATE[2:0]</u> bits. See section 6.5 for details.

6.2.3.2 FIFO Mode

The digital front-end gives access to RAM as a 1024-sample FIFO for waveform playback with <u>PLAY MODE[1:0]</u> bits set to 0x1. FIFO entries are appended every time waveform samples are written in the <u>REFERENCE</u> register. Digital samples are represented as 12-bit unsigned values. If <u>OE</u> bit is set to 0x1, the FIFO entries are read automatically out of the FIFO at a rate set by <u>PLAY SRATE[2:0]</u> bits. See section 6.6 for details.

6.2.3.3 RAM Playback Mode

RAM Playback mode is selected with <u>PLAY MODE[1:0]</u> bits set to 0x2. In RAM Playback mode, on-chip RAM of 2 kB is used to store arbitrary haptic waveforms as waveform amplitude samples in 12-bit unsigned format. The waveform is sampled at a rate set by <u>PLAY SRATE[2:0]</u> bits. See section 6.7 for more details.

6.2.3.4 RAM Synthesis Mode

RAM Synthesis mode is selected with bits <u>PLAY MODE[1:0]</u> set to 0x3. With this mode, the BOS1921/BOS1931 uses the Waveform Synthesizer (WFS) to generate waveforms using parameters stored in the 2 kB RAM. RAM Synthesis mode allows generation of sine waveforms of various amplitudes and frequencies without having to send every sample of the waveform to RAM as is the case with RAM Playback mode. This allows complex waveforms to be produced with minimal data communication. See section 6.8 for details.

6.2.4 Piezo Sensing (BOS1921 Only)

The BOS1921 can use a piezo actuator as a force sensor by measuring the voltage across its terminals.

The BOS1921 also features an embedded sensing comparator that can be configured to automatically trigger an already programmed waveform.

The GPIO pin can inform the MCU that a sensing voltage event occurred or a triggered waveform has finished playing using GPIOSEL[2:0] bits. Voltage sensed is available with SENSE VALUE[11:0] bits, which can be read at any time when sensing is activated (CONFIG.SENSE bit set to 0x1) and is useful for MCU-based customized sensing algorithms. See section 6.4 for more detail.

The sensing resolution can be selected between 7.6 mV and 54.5 mV as detailed in Table 10.

Product Datasheet



Table 10: Sensing Ranges List

REGISTER	REGISTER VALUE	INPUT RANGE (V)	SENSING RESOLUTION (V)
CONFIG.GAINS	0x1	±13.25	0.0076
<u>CONFIG.GAINS</u>	0x0	±95	0.0545

6.2.5 Continuous Mode

With RAM Synthesis or RAM Playback mode, it is possible to play a waveform for an indefinite amount of time without the intervention of an external MCU. This feature is well suited for cooling or micropump applications that need to operate for long periods of time while minimizing overall system power and resource usage.

6.2.6 SLEEP Mode

When no output waveform is being requested, no sensing is needed (BOS1921 only) and the output is disabled (bit <u>OE</u> set to 0x0), the device can enter in one of its two low-power modes by the use of the bit <u>DS</u>: IDLE or SLEEP mode. By default, power mode is IDLE (bit <u>DS</u> set to 0x0). SLEEP mode is selected when bit <u>DS</u> is set to 0x1.

In SLEEP mode, the BOS1921/BOS1931 preserve its RAM and the contents of the registers by default (RET bit set to 0x0). By setting RET bit set to 0x1, SLEEP mode does not preserve RAM and neither the contents of the registers to reduce the power consumption. Note that to reduce the total quiescent current of the device, the following should be done:

- Disabled state retention (set RET bit to 0x1)
- Power off VDDIO supply.

The BOS1921/BOS1931 wakes up from SLEEP mode when a communication occurs on its I²C/I3C interface (the data will not have any effect on the configuration of the registers).

6.2.7 Low Latency Startup

The BOS1921/BOS1931 features a fast start-up time. From IDLE or SLEEP mode, the device takes less than 300 μ s to start playing the waveform. This makes the device a very small contributor to system latency.

6.2.8 Device Reset

The BOS1921/BOS1931 device has software-based reset functionality. When <u>RST</u> bit is set to 0x1, all registers are set to their default value and IC goes in IDLE state. <u>RST</u> bit self-clears once the reset is complete.

The following sequence must be done to safely reset the device while playing a waveform in FIFO or Direct mode:

- 1. Set CONFIG.OE bit must be set to 0x0.
- 2. Wait for the device to be in IDLE by polling IC STATUS.STATE[1:0] bits.
- 3. Reset the device by setting RST bit to 0x1.

6.2.9 Device Synchronization

Multiple BOS1921/BOS1931 devices can be synchronized using SYNC pin to play haptic waveforms simultaneously on their respective piezo actuator with a phase delay of less than 2 μs between them.

Product Datasheet



Synchronization is achieved by connecting the SYNC pin of all devices with each other. A 10 k Ω pull-up resistor is needed between SYNC node and V_{DDIO} . The sequence to use device synchronisation is the following:

- 1) Set OE bit and SENSE bit to 0x0 on all devices.
- 2) Set SYNC bit to 0x1 on all devices.
- 3) For Each devices set OE bit to 0x1. The devices will wait on each other before starting to play the waveform and will synchronize the haptic waveforms within less than 2 µs during playback.

Note that SYNC pin must be tied to ground if unused.

6.2.10 Adjustable Current Limit

The maximum current of the power converter must be limited to avoid damage to both the L_1 inductor and the BOS1921/BOS1931 device by selecting the appropriate R_{sense} value (see section 7.5.3). The BOS1921/BOS1931 determine the current flowing through the L_1 inductor by measuring the voltage drop across R_{sense} , which is positioned between the RP/VDD and RM pins.

The current limit flowing through SW pin should be selected based on the following:

- Ensure that the current is lower than the saturation limit of the inductor L1.
- Ensure that the current is high enough to allow sufficient energy transfer to and from the piezo actuator.

The solution should be tested during its worst-case operation to ensure that the BOS1921/BOS1931 meets the bandwidth requirement of the application.

6.2.11 Internal Charge Pump

The BOS1921/BOS1931 has an internal 5 V charge pump which requires a 0.1 μ F capacitor (C_{PUMP}) with a 6.3 V voltage rating or more to be connected on HV pin.

6.2.12 Energy Recovery

The BOS1921/BOS1931 IC implements bidirectional power transfer: input to output, and output to input. Such architecture enables the recovery of the energy accumulated on the capacitive load and transfers it back to the input. The internal controller automatically determines the direction of the power flow during waveform playback.

6.2.13 Unidirectional Power Input (UPI)

The BOS1921/BOS1931 can sink and source current from the power delivery network (PDN) during normal operation thanks to its energy recovery feature. If the PDN can't sink current (e.g., if the device is powered by batteries), the Unidirectional Power Input (UPI) must be configured by setting UPI bit to 0x1. UPI allows the device to appear as a resistive load to the power supply (the device only sinks current) and reducing RMS current flowing in the PDN. UPI does not affect the efficiency of the BOS1921/BOS1931, but it causes the following to happen:

- First, power is drawn from the input source when the amplitude of the output waveform increases.
- Second, energy recovered accumulates on the input capacitor (C_{VDD}) when the amplitude of the output waveform decreases.

Energy accumulation on the C_{VDD} capacitor causes the voltage at VDDP pin to increase, as shown in Figure 16. The voltage increase can be adjusted by first calculating the maximum energy that may be recovered



from the load and then sizing C_{VDD} appropriately to achieve the desired voltage increase (see section 7.5.5). Voltage at VDDP pin should never exceed 5.5 V.

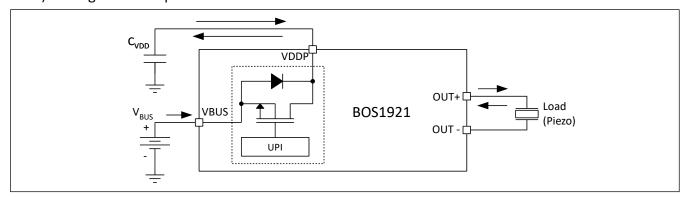


Figure 15: Block diagram of the Unidirectional Power Input (UPI)

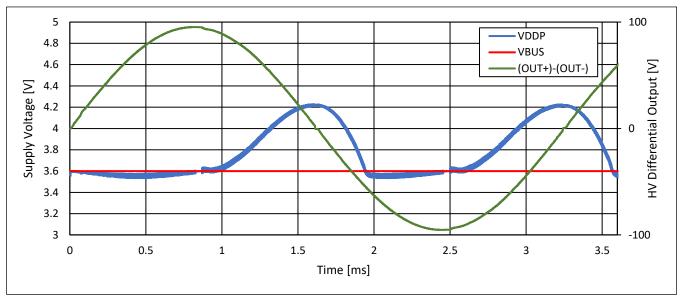


Figure 16: Voltage increases at VDDP pin during energy recovery when bit \underline{UPI} is set to 0x1, $C_{VDD} = 100 \ \mu F$, $C_{Load} = 100 \ nF$

6.2.14 Adjustable Internal Clock

The internal clock oscillator frequency is trimmed during fabrication using hardware fuses. When initialized, the BOS1921/BOS1931 retrieves the hardware fuse values and push them to the TRIM block to adjust the oscillator frequency based on the fuse values (see Figure 34). The <u>TRIM</u> register allows modifying the TRIM values to adjust oscillator frequency.

The feature can be used to match the external system clock frequency with the BOS1921/BOS1931 internal clock frequency, which is used to determine the FIFO read-out rate. This might be needed to minimize waveform distortion if the user writes waveform data at a constant rate to the FIFO, without managing space available in it. To successfully adjust internal clock frequency, OE bit needs to be set to 0x0.

Product Datasheet



The internal oscillator can be adjusted with the following sequence:

- 1. Set CONFIG.OE bit to 0x0.
- 2. Set TRIM.TRIMRW[1:0] bits to one of the following values:
 - a. Set to 0x1 to latch the Hardware Fuses to Trim Block and push them to the TRIM register, or
 - b. Set to 0x2 to retrieve the oscillator trim value contained in the TRIM block and push the value to the TRIM register.
- 3. Wait 1 ms.
- 4. Read <u>TRIM.TRIM OSC[5:0]</u> bits (using bits <u>COMM.RDADDR[4:0]</u>) to get the internal oscillator trim value specific to the device.
- 5. In one transaction, set the TRIM register with the following field:
 - a. TRIM OSC[5:0] bits set to the desired value.
 - b. TRIMRW[1:0] bits set to 0x3 to write TRIM OSC[5:0] value to TRIM block.

The same procedure can be used to adjust the internal 1.8 V regulator voltage (pin REG) using bits TRIM.TRIM REG[2:0] instead of TRIM.TRIM OSC[5:0] bits.

6.2.15 Fault and Warning Behaviour

This section lists the various faults detected by the device. Note that faults detected by the device may be caused by the following:

- Device operating outside of its safe operating conditions.
- Wrong component value (e.g., R_{sense}, C_{HV}, C_{VDD} or L₁).
- Noise induced by improper printed circuit board layout.

6.2.15.1 Overvoltage Fault

The overvoltage fault is triggered to prevent damage when voltage level on OUT+ or OUT- pin relative to V_{BUS} voltage is outside safe operating conditions. The fault is triggered in the following situations:

- When playing haptic waveforms with high gain in the following conditions:
 - OE bit set to 0x1.
 - SENSE bit set to 0x0.
 - o GAIND bit set to 0x0.
 - Voltage level on OUT+ pin relative to V_{BUS} is above 100 V or voltage level on OUT- pin relative to V_{BUS} is below -100 V.
- When playing haptic waveforms with low gain in the following conditions:
 - OE bit set to 0x1.
 - SENSE bit set to 0x0.
 - o GAIND bit set to 0x1.
 - Voltage level on OUT+ pin relative to V_{BUS} is above 14 V or voltage level on OUT- pin relative to V_{BUS} is below -14 V.
- When using piezo actuator sensing with the BOS1921 and high gain in the following conditions:
 - OE bit set to 0x1.
 - SENSE bit set to 0x1.
 - o GAINS bit set to 0x0.
 - Voltage level on OUT+ pin relative to V_{BUS} is above 100 V or voltage level on OUT- pin relative to V_{BUS} is below -100 V.

Product Datasheet



- When using piezo actuator sensing with the BOS1921 and low gain in the following conditions:
 - o OE bit set to 0x1.
 - SENSE bit set to 0x1.
 - o GAINS bit set to 0x1.
 - Voltage level on OUT+ pin relative to V_{BUS} is above 14 V or voltage level on OUT- pin relative to V_{BUS} is below -14 V.

If an overvoltage condition is detected during waveform generation, the following events occur:

- IC STATUS.OVV fault bit is set.
- IC STATUS.STATE[1:0] bits are changed to 0x3 (ERROR state).
- Output voltage ramp down to VDD.

The <u>OVV</u> bit will clear automatically and the BOS1921/BOS1931 state will change to IDLE (bits <u>STATE[1:0]</u> set to 0x0) with the following conditions:

- OE bit is 0x0.
- Output voltage is lower than the maximum allowed *V_{OUT(FS)}*.

6.2.15.2 Output Short Circuit Fault

The BOS1921/BOS1931 has an output short circuit protection to prevent excessive current to flow because of a shorted load. In case a short circuit is detected, the following events occur:

- IC STATUS.SC fault bit is set.
- IC STATUS.STATE[1:0] bits are changed to 0x3 (ERROR state).
- Output voltage ramp down to VDD.

The <u>SC</u> bit will clear automatically and the BOS1921/BOS1931 state will change to IDLE (bits <u>STATE[1:0]</u> is 0x0) with the following conditions:

- Bit OE is 0x0.
- Output voltage is lower than the maximum allowed V_{OUT(FS)}.

6.2.15.3 Over Temperature Fault

The BOS1921 has an internal temperature sensor that puts the BOS1921/BOS1931 in ERROR state in case the die junction temperature exceeds 145 °C. In this case, the following events occur:

- IC STATUS.OVT fault bit is set.
- IC STATUS.STATE[1:0] bits are changed to 0x3 (ERROR state).
- Output voltage ramp down to VDD.

The OVT bit will clear automatically and the BOS1921/BOS1931 state will change to IDLE (STATE [1:0] bits are 0x0) with the following conditions:

- OE bit is 0x0.
- Output voltage is lower than the maximum allowed V_{OUT(FS)}.

The low power dissipation of the BOS1921/BOS1931 makes it unlikely that its temperature will reach 145 °C even when it is continuously operated at the maximum Z_L in the operating temperature range T_A .



6.2.15.4 Under Voltage Fault

The BOS1921/BOS1931 monitor V_{BUS} , and if its voltage is below 2.875 V during waveform generation, the following events occur:

- IC STATUS.UVLO bit is set.
- IC STATUS.STATE[1:0] bits are changed to 0x3 (ERROR state).
- Output voltage ramp down to V_{DD} .

<u>UVLO</u> bit will self-clear and the BOS1921/BOS1931 state will change to IDLE (<u>STATE[1:0]</u> bits are set to 0x0) with the following conditions:

- OE bit is 0x0.
- Output voltage is lower than the maximum allowed V_{OUT(FS)}.

6.2.15.5 Current Detection Status Fault

For proper operation, the BOS1921 monitors the current using R_{sense} resistor connected to RP and RM pins. If no current is detected during waveform generation, the following event occurs:

- IC STATUS.IDAC fault bit is set.
- IC STATUS.STATE[1:0] bits are changed to 0x3 (ERROR state).

<u>IDAC</u> errors are typically triggered by incorrect component sizing (see section 7.5) or inadequate waveform data. If component sizing and waveform data are correct, see section 6.2.18 for details on other circumstances that can cause an IDAC error and strategies to avoid them.

To recover from an IDAC error, a software reset must be done using <u>CONFIG.RST</u> bit. <u>IC_STATUS.IDAC</u> bit does not self-clear.

6.2.15.6 Maximum Power Warning

During waveform playback, if the current in R_{sense} is equal or greater to the current limit defined in section 7.5.3, a maximum power warning is raised, and the following happens:

- IC STATUS.MXPWR warning bit is set.
- IC STATUS.STATE[1:0] bits remain 0x2 (RUN state).
- The waveform continues to play but is likely distorted.

<u>IC STATUS.MXPWR</u> bit does self-clears when the current in R_{sense} is lower than current limit defined in section 7.5.3.

6.2.15.7 Brownout

The BOS1921/BOS1931 has internal brownout protections and if V_{REG} goes below 1 V. In this case, the following event occurs:

The chip issues a reset signal, and all registers are set to their default values.

When V_{REG} goes back to its specified operating voltage, the BOS1921/BOS1931 will be in IDLE state (STATE[1:0] bits set to 0x0).

6.2.16 Output Timeout

Setting <u>TOUT</u> bit to 0x1 enables a timeout mechanism that forces the BOS1921 into SLEEP mode if no new communication has been received within 4 ms while playing a waveform in Direct or FIFO mode (<u>PLAY_MODE[1:0]</u> bits set to 0x0 or 0x1).

Note that PLAY SRATE[2:0] bits are reset to 0x7 when the device enters SLEEP following a timeout event.

Product Datasheet



More specifically, the BOS1921/BOS1931 enters SLEEP mode when the following conditions are met:

- COMM.TOUT bit is set to 0x1.
- <u>CONFIG.OE</u> bit is set to 0x1.
- PLAY MODE[1:0] bits are set to 0x0 or 0x1.
- The FIFO is empty when using FIFO mode (PLAY MODE[1:0] bits set to 0x1).
- The BOS1921/BOS1931 did not receive any communication on its digital interface for more than 4 ms.

6.2.17 Interrupt

The BOS1921/BOS1931 features interrupt capabilities for different events enabled with the <u>INT_ENABLE</u> register. The status of interrupts is read with the <u>INT_STATUS</u> register.

The GPIO pin can be used to notify the MCU when one of the interrupts has occurred by setting GPIOSEL[2:0] bits set to 0x5.

There are up to 7 distinct interrupt events that can be configured. Each event can be enabled by programming the corresponding bit in the <u>INT_ENABLE</u> register. A bit in the <u>INT_STATUS</u> register is set when the condition corresponding to its event changes from *false* to *true* (i.e. rising edge condition).

All the <u>INT_STATUS</u> register bits are automatically cleared in the following situations:

- INT STATUS register is read
- A soft reset is performed
- Device goes to SLEEP

The <u>INT_STATUS</u> register bits are not cleared when setting its corresponding <u>INT_ENABLE</u> register bits to 0x0.

Note that if the interrupt condition is already *true* when the interrupt is enabled, the interrupt can be immediately triggered and its corresponding <u>INT STATUS</u> register bits will be set to 0x1. It is thus recommended to clear any existing interrupt by reading <u>INT STATUS</u> register after enabling interrupts.

Note that the desired PLAY MODE bits should be set prior to configure interrupts.

The <u>INT_ENABLE</u> register can be used to enable interrupts on the following events:

- <u>IE FHE</u> bit enables an interrupt when FIFO is at least half empty. Interrupt triggers when FIFO is more than half empty.
- <u>IE STCHG</u> bit enables an interrupt when the BOS1921/BOS1931 state change. Interrupt triggers when STATE[1:0] bits changed.
- <u>IE MXERR</u> bit enables an interrupt when there is a difference between the waveform played on the output and the setpoint.
- <u>IE SENSF</u> bit enables an interrupt when a sensing event occurred (BOS1921 only), i.e., it triggers when <u>SENS_FLAG</u> bit is set to 0x1.
- <u>IE PLAY</u> bit enables an interrupt when the waveform playback status is set, i.e., it triggers when PLAYST bit is set to 0x1.
- <u>IE MAXP</u> enables an interrupt when a maximum power error occurred, i.e., it triggers when <u>MXPWR</u> bit is set to 0x1.
- <u>IE ERR</u> enables an interrupt when the BOS1921/BOS1931 state changes for ERROR, i.e., it triggers when STATE[1:0] bits are set to 0x3.

Product Datasheet



The following sequence presents an example on how to use the interrupt feature along with FIFO mode:

- 1. Set CONFIG.PLAY MODE[1:0] bits to 0x1 to select FIFO mode.
- 2. Set bit CONFIG.OE to 0x1 to enable the output.
- 3. Set INT ENABLE.IE FHE bit to 0x1 to enable the interrupt when the FIFO is half empty.
- 4. Set <u>COMM.RDADDR[4:0]</u> bits to 0x1F and read the <u>INT STATUS</u> register to clear existing interrupt.
- 5. Set GPIOSEL[2:0] bits to 0x5 to output the interrupt on the GPIO pin.
- 6. Set <u>COMM.RDADDR[4:0]</u> bits to 0x11, read <u>FIFO STATE</u> register and use <u>FIFO STATE.FIFO SPACE[9:0]</u> bits to determine space available in FIFO for new data.
- 7. Write as many 12-bit waveform data as possible according to space available in FIFO into the REFERENCE register.
- 8. Wait for a falling edge on the GPIO pin to occur, which indicates an interrupt occurred.
- 9. Set <u>COMM.RDADDR[4:0]</u> bits to 0x1F and read the <u>INT_STATUS</u> register. The <u>INT_STATUS.IS_FHE</u> bit should be 0x1 and will be immediately cleared after reading register.
- 10. Repeat steps 5 to 8 until the desired waveform is completed.

6.2.18 Output Bridge Protection

The BOS1921/BOS1931 includes a protection preventing the internal output bridge from changing polarity if a voltage greater than 4.4 V is present between the OUT+ and OUT- pins when playing a waveform. This protection is essential especially for BOS1921 when using sensing feature since the voltage on the piezoelectric ceramic terminal increases or decreases as it is deformed. Residual voltage can thus be present on the output of the BOS1921 when a waveform is requested to be played.

The bridge protection triggers in the following conditions:

- Play a positive haptic waveform when a negative voltage smaller than -4.4 V has built up on the piezoelectric ceramic.
- Play a negative haptic waveform when a positive voltage greater than 4.4 V has built up on the piezoelectric ceramic.

The bridge protection triggering causes a waveform played in the wrong polarity with or without IDAC error (see section 6.2.15.5). The bridge protection triggering can be caused by incorrect component sizing (see section 7.5) or inadequate waveform data.

To prevent the bridge protection to trigger, one could reset the voltage on the piezoelectric ceramic before starting to play the haptic waveform. This can be achieved by playing one of the following sets of data before the desired haptic waveform:

- Several 0 V data points.
- Voltage data points increasing from -2 V to 0 V if a positive waveform is intended to be played.
- Voltage data points decreasing from 2 V to 0 V if a if a negative waveform is intended to be played.

6.3 Digital Interface

A MIPI I3C target port enables communication with the BOS1921/BOS1931. I3C is backward compatible with legacy I²C devices, but I3C bus supports significantly higher speed. It is used to write data to the registers, whose content can also be read back.



6.3.1 General Communication Protocol

The controller MCU can transfer data with the target BOS1921/BOS1931 using I3C or I²C standards.

6.3.1.1 Write Transactions

Both I²C and I3C can do write transactions with the following:

- The first byte contains the register address corresponding to the register to write to.
- Two bytes of register data; the first byte corresponds to the MSBs of the register data and the second byte corresponds to the LSBs of register data.

To write more than one register, three behaviours are possible:

- Register address = 0x00: All subsequent 2-byte words will automatically be written to the <u>REFERENCE</u> register. The communication frame must be stopped from accessing the other registers.
- 2. <u>STR</u> bit set to 0x1: The register address other than 0x00 will automatically be incremented every two bytes to allow writing multiple registers in the same transmission frame and reduce the number of bits used in the communication. The communication frame must be stopped to skip the remaining register addresses.
- 3. <u>STR</u> bit set to 0x0: A byte of address for each target register must be sent (no automatic address incrementation).

6.3.1.2 Read transactions

Each communication transaction returns two bytes of data corresponding to the value of the register whose address is specified in RDADDR[4:0]. Burst reads are not supported, i.e., it is not possible to read multiple registers in a single access. However, the RDADDR[4:0] bits can automatically be incremented by 1 after each read by setting RDADDR[4:0] bits once with the address of the first register to be read, then issuing a sequence of reading accesses to read a series of registers.

6.3.2 I3C Interface

The I3C target functionality implemented in the BOS1921/BOS1931 is based on MIPI® Alliance Specification for I3CSM, version 1.1.1. I3C is a 2-wire bidirectional serial bus which always has one controller and one or more targets. The two wires are designated SDA and SCL: SDA is a bidirectional data signal, SCL is a clock signal. They connect respectively to BOS1921/BOS1931 SDA and SCL pins.

Table 11: Serial interface pin description

PIN NAME	PIN DESCRIPTION
SDA	Bidirectional Data Signal
SCL	Controller Clock Signal

I3C communication is initiated by the controller which generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions. All I3C communication occurs within a frame. The basic frame begins with a START, followed by the header, the data, and a STOP (see Figure 17 for more details). The header following a START allows for bus arbitration. The controller uses the header to address target device(s). Each target is addressed by a unique 7-bit target address plus a read-write bit.



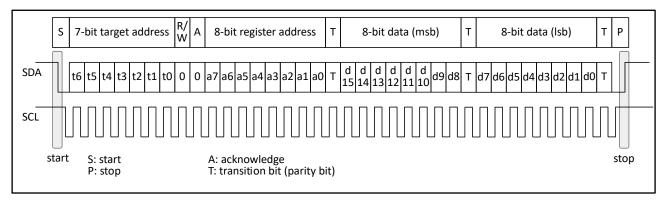


Figure 17: Typical I3C write communication frame

The I3C bus uses transitions on SDA while the clock is at logic high to indicate START and STOP conditions. A high-to-low transition on the SDA signal indicates a START, and a low-to-high transition indicates a STOP. All devices share the same SDA signals through a bidirectional bus using a wired-AND connection. The data transition on SDA must occur while the clock period is low.

The implemented I3C target of the BOS1921/BOS1931 has a legacy I²C default static address (7'h44). The 4 LSBs of the address can be changed by assigning the I2C_ADDR bits. The BOS1921/BOS1931 will act as an I²C target using that address up until it is assigned a dynamic address. Once assigned a dynamic address, the BOS1921/BOS1931 will only operate as an I3C target until it is reset.

A 50 ns spike filter is included in the BOS1921/BOS1931. By default, the spike filter is active at power up. To operate in I3C, the user first needs to write to the broadcast address 0x7E at I²C speed. The filter will automatically be deactivated, and the user can then use I3C communication speed.

6.3.2.1 I²C Communication

The BOS1921/BOS1931 acts by default as an I²C target using its static address (7'h44). Figure 18 shows a basic data-transfer sequence with I²C static addressing. Following a START, the controller generates the 7-bit target address and the read-write (R/W) bit to communicate with a target device. The target device then holds the SDA signal low during the next clock period to indicate acknowledgment to the controller. When this acknowledgment occurs, the controller transmits the next byte(s) of the sequence.

There are two addresses used to access a register. The first is the target address used to select the BOS1921/BOS1931. The second address is an 8-bit register address sent in the first byte transferred in a write operation. The register address points to a specific register (section 6.10). Automatic increments of address pointer can be set using STR bit. The address pointer is automatically incremented every two bytes, allowing continuous write operations.



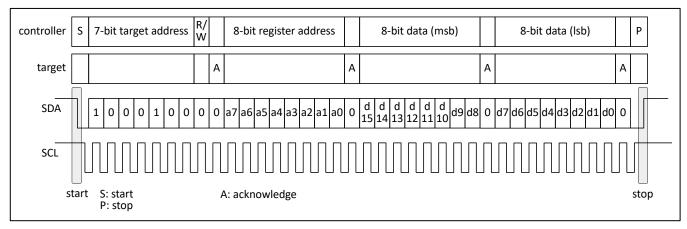


Figure 18: Basic data transfer write sequence with I²C static addressing

Figure 19 presents a typical communication sequence in I²C. MSB is always sent first.

A typical write sequence from power up is the following:

- 1. Write with static address 0x44 with dummy data to wake-up the device.
- 2. Configure registers as needed.

Figure 20 presents a single communication transaction to access several main registers using <u>STR</u> bit set to 0x1 to access several main registers.

A 50 ns spike filter is included and activated at power up.

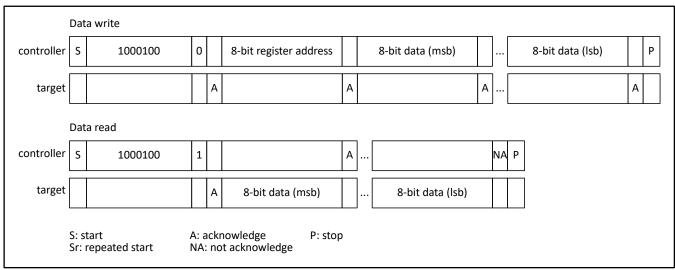


Figure 19: Typical data-transfer sequences with I²C static addressing



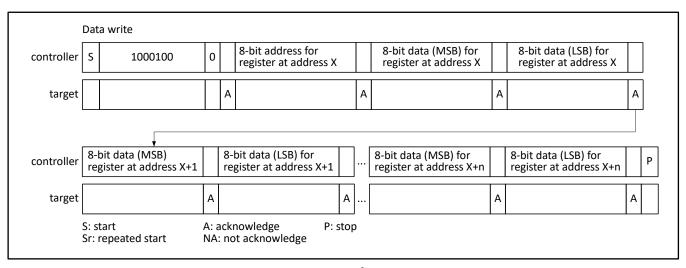


Figure 20: Typical data-transfer sequences with I²C static addressing with <u>STR</u> bit set to 0x1

6.3.2.2 I3C Communication

BOS1921/BOS1931 I3C interface is compliant with MIPI® Alliance Specification for I3CSM, version 1.1.1 and features the following:

- 1. Target only
- 2. SDR (Single Data RATE) up to 12.5 MHz
- 3. I²C compatibility with static address: 7'h44
- 4. Supports basic Common Command Codes (CCC) (see Table 12 for more details)
- 5. Does not support Hot Join (HJM)
- 6. Does not support In-Band Interrupt (IBI)
- 7. Provisional ID = 0x08A207814000 (see Table 13 or more details)
- 8. Bus Characteristic Register = 0x00
- 9. Device Characteristic Register = 0x25

Table 12: Common Command Codes (CCC) support

COMMAND NAME	TYPE	CODE	DESCRIPTION
ENEC	Broadcast	0x00	Enable events command
DISEC	Broadcast	0x01	Disable events command
ENTAS0	Broadcast	0x02	Enter activity state 0
ENTAS1	Broadcast	0x03	Enter activity state 1
ENTAS2	Broadcast	0x04	Enter activity state 2
ENTAS3	Broadcast	0x05	Enter activity state 3
RSTDAA	Broadcast	0x06	Reset dynamic address assignment
ENTDAA	Broadcast	0x07	Enter dynamic address assignment
ENEC	Direct	0x80	Enable events command
DISEC	Direct	0x81	Disable events command
ENTAS0	Direct	0x82	Enter activity state 0
ENTAS1	Direct	0x83	Enter activity state 1

Product Datasheet



COMMAND NAME	TYPE	CODE	DESCRIPTION
ENTAS2	Direct	0x84	Enter activity state 2
ENTAS3	Direct	0x85	Enter activity state 3
RSTDAA	Direct	0x86	Reset dynamic address assignment
SETNEWDA	Direct	0x88	Set new dynamic address
GETPID	Direct	0x8D	Get provisional ID
GETBCR	Direct	0x8E	Get bus characteristics register
GETDCR	Direct	0x8F	Get device characteristics register
GETSTATUS	Direct	0x90	Get device status
GETCAPS	Direct	0x95	Get HDR Capability

Table 13: Defaults provisional ID details

FIELD	WIDTH	VALUE
Provisional ID (default)	48	0x08A207814000
Manufacturer ID	15	0x0451
Part ID	16	0x0781
Instance ID	4	0x4 (I2C_ADDR[3:0])
Vendor Defined	12	0x000

The BOS1921/BOS1931 will operate as an I3C target only after it is assigned a dynamic address by the controller using command ENTDAA with I²C timing constraints. A dummy write to address 0x7E can be performed prior to ENTDAA command to clear the 50 ns spike filter and enable communication at I3C speed without I²C constraints. A typical write sequence from devices power up is the following:

- 1. Send start condition with broadcast address 0x7E at I²C speed to clear I²C spike filter.
- 2. Send ENTDAA command.
- 3. Wake-up the chip with a dummy write.
- 4. Configure registers as needed.

6.3.3 Resolving I²C/I3C Address Conflicts

It is possible to connect multiple BOS1921/BOS1931 on the same I²C or I3C bus. By default, they all have the same address, so they all respond simultaneously to the same commands. However, it is possible to assign different addresses to each IC to allow accessing each one individually. The process requires to first configure the GPIO as a "Chip Select" before setting the I2C_ADDR[3:0] bits. The procedure is the same for I²C or I3C protocols, but I3C mode requires the additional steps of resetting and reassigning the dynamic address after having set I2C_ADDR[3:0] bits (see section 6.3.2.2).

Product Datasheet



The steps to reassign the I²C target address are the following:

- 1. Set the COMM.GPIODIR bit to 0x1 bit to use the GPIO as an input.
- 2. Apply a logic level low on the target device GPIO pin.
- 3. Set the <u>SUP_RISE.I2C_ADDR[3:0]</u> bits with the desired target device address. The new address will take effect immediately.
- 4. Wait at least 1 μ s after the completion of the I²C access performed during the previous step, after which the GPIO pin no longer needs to be used to access to the target device.
- 5. Using the new I²C address, perform a register access to make sure that the address change was successful.

Note that in I3C Mode the <u>SUP_RISE.I2C_ADDR[3:0]</u> bits are used to set the 4-bit Instance ID (i.e., bits [15:12] of the Provisional ID, see Table 13).

6.4 Piezo Actuator Sensing (BOS1921 Only)

The BOS1921 can sense the voltage across a piezo actuator and use it as a force sensor. The sensed voltage can be read to implement a custom detection algorithm.

The device can also be configured to generate an event when a sensing voltage threshold has been crossed. The sensed voltage event can result in the following:

- 1. Sense Voltage Alert: alert a MCU of the sensed voltage event.
- 2. Sense Voltage Trigger for Automatic Haptic Playback: The communication frame must be stopped to access other registers.

The following notes apply to the piezo actuator sensing feature:

- The <u>CONFIG.SENSE</u> bit activates the sensing of the actuator voltage without forcing a voltage on OUT+ and OUT- pins. This bit allows the piezo actuator voltage to vary freely as the user physically interacts with it.
- The <u>CONFIG.OE</u> bit enables the measurement of the HV pin voltage by the device, which is required for sensing feature to work.
- No haptic waveform should be playing while setting <u>CONFIG.SENSE</u> bit to 0x1. Wait until the IC <u>STATUS.PLAYST</u> bit is 0x1 before setting <u>CONFIG.SENSE</u> bit to 0x1.
- When sensing is activated, no haptic waveform can be output.
- One can activate piezo actuator sensing feature after playing a haptic waveform by simply setting the CONFIG.SENSE bit to 0x1 (no need to reset the CONFIG.OE bit to 0x0 and set it back to 0x1).
- To stop the sensing feature, it is recommended to reset the device using <u>RST</u> bit to reset registers and RAM.

6.4.1 Sensed Voltage Reading

The sensed voltage can be read at any time to implement more complex sensing algorithms running in a MCU such as slope detection or voltage profile pattern recognition.

When sensing is activated, sensed voltage is continually updated and pushed to the <u>SENSE VALUE</u> register so the latest value can be read at any time. There is no required reading rate.

Note that <u>SENSE_VALUE[11:0]</u> bits set to 0x0 means that the differential voltage is 0 V. However, when the circuit is in sensing and no signal is generated by a piezo actuator, a negative differential voltage of approximately -350 mV is read.

Product Datasheet



The following bits of the SENSE VALUE register are used to read sensed voltage:

- <u>SENSE VALUE[11:0]</u> bits are the 12-bit signed representation of the sensed voltage.
- <u>SENSE</u> bit indicates if sensing mode is activated.

6.4.1.1 Polling Sequence Example

A typical communication sequence to poll the sensed voltage is as follows:

- 1. Set CONFIG.ONCOMP to 0x0 to prevent sensed voltage from triggering a sensing event.
- 2. Set **CONFIG.SENSE** to 0x1 to enable piezo actuator sensing.
- 3. Set CONFIG.OE to 0x1 to start sensing.
- 4. Read SENSE VALUE[11:0] bits.
- 5. Repeat the step 4) as needed.

6.4.2 Sense Voltage Alert

An internal sensing comparator allows to detect when the sensed voltage on the piezo actuator crosses a configurable threshold voltage. When the detection conditions are met, the <u>SENSE_FLAG</u> bit is set to 0x1. The SENSE_FLAG bit can be reset by reset <u>ONCOMP</u> bit to 0x0.

The sensing voltage alert settings are the following:

- <u>CONFIG.ONCOMP</u> bit enables the embedded comparator which triggers the alert. It must be set to 0x1 to enable comparison.
- <u>SENSING.SIGN</u> defines whether the voltage feedback value must be above or below the threshold for the detection to succeed.
- <u>SENSING.REP[2:0]</u> bits define how long the voltage must be above or below the threshold for detection to succeed (hold time).
- <u>SENSING.STHRESH[11:0]</u> bits define a differential voltage threshold to be crossed for the detection to succeed.
- SENSE VALUE.SENSE FLAG bit indicates when a detection has occurred.
- <u>COMM.GPIOSEL[2:0]</u> bits set to 0x6 configure the GPIO pin to indicate when a sense voltage alert
 has occurred (note that the interrupt mechanism can also be used by setting <u>GPIOSEL[2:0]</u> to
 0x5).

6.4.3 Sense Voltage Trigger for Automatic Haptic Playback

The BOS1921 can detect force on the piezo actuator and automatically play a pre-programmed waveform using FIFO (section 6.6), RAM Playback (section 6.7) or RAM Synthesis (section 6.8) modes with minimal intervention needed by the MCU.

GPIO pin can notify the MCU that the waveform playback is completed.

Product Datasheet



The following is used to enable and monitor Automatic Haptic Playback:

- A waveform must be armed (see section 6.8.7 for an example). The waveform must be armed again each time an automatic waveform playback occurs.
- <u>CONFIG.SENSE</u> bit enables piezo actuator sensing. The bit self-clears and must be enabled again each time an automatic waveform playback occurs.
- <u>CONFIG.ONCOMP</u> bit enables the embedded comparator which triggers the automatic waveform playback. <u>ONCOMP</u> bit must be disabled and then enabled again each time an automatic waveform playback occurs.
- <u>CONFIG.AUTO</u> bit enable Automatic Haptic Playback. The bit self-clears and must be enabled again each time an automatic waveform playback occurs.
- SENSE VALUE.SENSE FLAG bit indicates when a detection has occurred.
- IC STATUS.PLAYST bit indicates when waveform playback has finished.
- <u>COMM.GPIOSEL[2:0]</u> bits set to 0x6 configure the GPIO pin to notify that a sense voltage event has occurred. Note that the interrupt mechanism can also be used by setting <u>GPIOSEL[2:0]</u> to 0x5.

6.4.3.1 Sequence Example for Button Press Sensing with Automatic Playback

A typical communication sequence to configure a press button Automatic Haptic Playback is as follows:

- 1. Program waveform using RAM Playback (section 6.5) or RAM Synthesis (section 6.8) mode.
- 2. Set COMM.GPIOSEL[2:0] to 0x6 to be notified on the GPIO pin that a sense voltage event has occurred.
- 3. Set SENSING.REP[2:0] to 0x5 to set 2048 µs hold time.
- 4. Set SENSING.THRESH[11:0] to 0x7 to set 750 mV threshold.
- 5. Set <u>SENSING.SIGN</u> bit to 0x0 to trigger on a voltage above the threshold (detect an increasing voltage).
- 6. Set <u>CONFIG.AUTO</u> bit to 0x1 to play a pre-programmed RAM Playback or RAM Synthesis waveform automatically on a successful detection.
- 7. Set CONFIG.ONCOMP bit to 0x1 to enable the embedded sensing comparator.
- 8. Set CONFIG.SENSE bit to 0x1 to enable piezo actuator sensing.
- 9. Set **CONFIG.OE** bit to 0x1 to start sensing.

Note that all bits in CONFIG register may be set in the same I²C/I3C instruction.



6.4.3.2 Sequence Example for Button Release Sensing with Automatic Playback

Once a detection occurred, sensing can be set again for a release button Automatic Playback using a communication sequence as follows:

- 1. Set <u>CONFIG.ONCOMP</u> bit to 0x0 to reset the sensing comparator.
- 2. Arm the next waveform depending on playback mode used as follows:
 - a. RAM Playback: issue an RAM PLAYBACK WFS command.
 - b. RAM Synthesis: issue an RAM Synthesis WFS command
- 3. Set <u>SENSING.REP[2:0]</u> to 0x5 to set 2048 µs hold time.
- 4. Set SENSING.THRESH[11:0] bits to 0xFFE to set -200mV threshold.
- 5. Set <u>CONFIG.SIGN</u> to 0x1 to trigger a haptic playback on voltage below the threshold (detect a decreasing voltage).
- 6. Set **CONFIG.ONCOMP** to 0x1 to enable the sensing comparator.
- 7. Set <u>CONFIG.SENSE</u> bit to 0x1 to enable piezo actuator sensing.
- 8. Set <u>CONFIG.AUTO</u> bit to 0x1 to play a pre-programmed RAM Playback or RAM Synthesis waveform automatically on a successful detection.
- 9. Set CONFIG.OE to 0x1 to start sensing.

Note that all bits in **CONFIG** register may be set in the same I²C/I3C instruction.

6.5 Direct Mode

In Direct mode (<u>PLAY MODE[1:0]</u> bits set to 0x0), the haptic waveform samples are played as they are sent from the host MCU to the <u>REFERENCE</u> register. The rate at which the data is read to generate the haptic waveform is set by <u>PLAY SRATE[2:0]</u> bits. An interpolation is done between user samples to generate the output waveform when <u>PLAY SRATE[2:0]</u> bits are 0x1 to 0x7.

Data management and synchronization can be facilitated by setting <u>GPIOSEL[2:0]</u> bit to 0x5 and <u>IE_PLAY</u> to 0x1 to allow the corresponding GPIO to generate an interruption that notifies the MCU when the BOS1921/BOS1931 is ready to receive the next sample. Interpolation between user samples is done to generate the output waveform.

In Direct mode, the RAM is not used, and its content previously written using RAM Playback mode (section 6.7) or RAM Synthesis mode (section 6.8) is preserved.

Note that waveforms should begin and end with 0 V amplitude.

6.5.1 Typical Operation Sequence

The following sequence shows how to use Direct mode to play haptic waveforms:

- 1. Set COMM.GPIOSEL[2:0] bits to 0x1 to monitor when one more sample is ready to be sent.
- 2. Set <u>CONFIG.PLAY MODE[1:0]</u> bits to 0x0 to select Direct mode.
- 3. Set <u>CONFIG.OE</u> bit to 0x1 to enable output.
- 4. Write a waveform sample to the REFERENCE[11:0] bits.
- 5. On a GPIO pin falling edge, go to step 4. to send the next waveform sample to the device.
- 6. Set CONFIG.OE bit to 0x0 once the desired waveform is completed.



6.6 FIFO Mode

In FIFO mode, the device uses RAM to implement a 1024-sample FIFO. The FIFO entries are appended every time waveform data is written in the <u>REFERENCE</u> register. When output is enabled, the FIFO entries are read automatically out of the FIFO at a rate set by <u>PLAY_SRATE[2:0]</u> bits to output a haptic waveform. An interpolation is done between user samples to generate the output waveform when <u>PLAY_SRATE[2:0]</u> bits are 0x1 to 0x7.

Note the following:

- For waveform playback streaming, the FIFO data write rate must match the readout rate of the
 waveform playback set by <u>PLAY_SRATE[2:0]</u> bits to always keep valid data inside the FIFO. The
 <u>PLAYST</u> bit is set to 0x1 when the FIFO becomes empty, causing the FIFO to hold the last valid
 data and keep the output waveform in a steady state.
- Burst data transfers can be used to minimize the communication interface usage. Packets of 16-bit words can be sent in the same data payload to be written in the FIFO. The <u>FULL</u> bit is set when the FIFO becomes full and cannot accept more data. The <u>FIFO SPACE[9:0]</u> bits can be read to check available space before sending new data.
- In case OE bit is set to 0x0 during waveform playback, the waveform will continue to play until the FIFO is empty.
- When the FIFO is empty, the last FIFO entry will remain on the device output.
- It is recommended to start and end waveforms with 0 V.
- It is recommended to terminate waveforms with 0 V before setting the OE bit to 0x0, otherwise the output voltage will slowly decrease to 0 V.

6.6.1 FIFO Depth

FIFO mode uses the RAM to implement the FIFO. Using FIFO mode with the default FIFO depth of 1024 locations could overwrite any waveform previously programmed using RAM Playback and RAM Synthesis modes.

FIFO mode can be used jointly with either RAM Synthesis or RAM Playback mode by configuring the FIFO dimension with a smaller number of RAM locations using the FIFO DEPTH command.

6.6.2 Typical Operation Sequence

The following sequence shows how to use FIFO mode to play haptic waveforms:

- 1. Set CONFIG.PLAY MODE[1:0] bits to 0x1 to select FIFO mode.
- 2. Set <u>CONFIG.OE</u> bit to 0x1 to enable the output.
- 3. Set <u>COMM.RDADDR[4:0]</u> bits to 0x11 and read <u>FIFO_STATE</u> register.
 - a. If FIFO STATE.FULL bit is 0x1 skip to step 5.
 - b. If <u>FIFO STATE.FULL</u> bit is 0x0, use <u>FIFO STATE.FIFO SPACE[9:0]</u> bits to determine space available in FIFO for new data.
- 4. Write as many 12-bit waveform data as possible according to space available in FIFO into the REFERENCE register.
- 5. Repeat steps 3 and 4 until the desired waveform is completed.
- 6. Set CONFIG.OE bit to 0x0 once the desired waveform is completed.

Product Datasheet



In the above example, the output is enabled prior to start filling the FIFO with data. It is also possible to fill the waveform in the FIFO before enabling the output, and then add samples to the FIFO as needed.

6.7 RAM Playback Mode

In RAM Playback mode (<u>PLAY_MODE[1:0]</u> bits set to 0x2), a point-by-point waveform need to be stored in chronological order in the RAM using <u>BURST RAM_WRITE</u> command. The waveform is played when the output is enabled (<u>OE</u> bit is set to 0x1).

Note that waveforms should begin and end with 0 V amplitude.

6.7.1 RAM Programming

The samples are written to the RAM using <u>BURST RAM WRITE</u> command. More than one waveform can be stored in the RAM. The 2 kB RAM can store up to 1024 words of 16 bits. Each word is defined by 12-bit data in the same format as the <u>REFERENCE[11:0]</u> bits. Start and end addresses are defined using the <u>RAM PLAYBACK</u> command and indicate the samples to be fetched when the playback is initiated.

When playback starts, the data is read out sequentially at the sample rate set by <u>PLAY_SRATE[2:0]</u> bits. An interpolation is done between user samples to generate the output waveform when <u>PLAY_SRATE[2:0]</u> bits are 0x1 to 0x7.

Once the waveform has been played, it must be rearmed to be played again by writing the RAM start and end addresses again using the <u>RAM PLAYBACK</u> command. The waveform will immediately start if these addresses are set while <u>OE</u> bit is already set to 0x1.

No waveform should be playing while programming RAM to avoid unexpected behaviour.

6.7.2 Continuous Waveform Playback

A waveform can be played continuously by using the RAM PLAYBACK command with the following field:

- 1. Set the RPT field to 0x1.
- 2. Set the <u>REPEAT START ADDRESS[9:0]</u> to the RAM address at which the desired continuous waveform starts.
- 3. Set the END ADDRESS[9:0] to the RAM address at which the desired continuous waveform goes back to the REPEAT START ADDRESS[9:0].
- 4. Set the <u>START ADDRESS[9:0]</u> to the RAM address at which the waveform starts. The <u>START ADDRESS[9:0]</u> may be different or identical to the <u>REPEAT START ADDRESS[9:0]</u>.

The <u>RAM PLAYBACK</u> command allows playing an initial waveform segment only once before looping over an adjacent segment continuously. This is done by specifying a <u>REPEAT START ADDRESS[9:0]</u> located between the <u>START ADDRESS[9:0]</u> and the <u>END ADDRESS[9:0]</u>. The segment between <u>START ADDRESS[9:0]</u> and <u>REPEAT START ADDRESS[9:0]</u> will be played once, then the segment between <u>REPEAT START ADDRESS[9:0]</u> and <u>END ADDRESS[9:0]</u> will be repeated continuously. By specifying the <u>START ADDRESS[9:0]</u> the same as the <u>REPEAT START ADDRESS[9:0]</u>, the entire segment is repeated.

To end a waveform being played continuously, a new <u>RAM PLAYBACK</u> command must be issued with <u>RPT</u> field set to 0x0 and the <u>END ADDRESS[9:0]</u> equals to or greater than the <u>END ADDRESS[9:0]</u> of the previous command (the <u>START ADDRESS[9:0]</u> and <u>REPEAT START ADDRESS[9:0]</u> fields will be ignored). Specifying an <u>END ADDRESS[9:0]</u> greater than the previously entered <u>END ADDRESS[9:0]</u> allows a final waveform segment to be played only once. Specifying an <u>END ADDRESS[9:0]</u> smaller than the previous <u>END ADDRESS[9:0]</u> is not advised as it can result in unpredictable behaviour.

Product Datasheet



It is also possible to send consecutive <u>RAM PLAYBACK</u> commands with <u>RPT</u> field set to 0x1. When a segment is being played continuously and a new <u>RAM PLAYBACK</u> command is received with <u>RPT</u> field set to 0x1, the following applies:

- The END ADDRESS[9:0] of the new command must be equal to or greater than the previously entered END ADDRESS[9:0].
- The REPEATED START ADDRESS of the new command must be smaller than or equal to the new END ADDRESS[9:0].
- The <u>START ADDRESS[9:0]</u> field is ignored.
- If REPEATED START ADDRESS is greater than the previous END ADDRESS[9:0], the segment between the previous END ADDRESS[9:0] and the new REPEATED START ADDRESS, referred as the *middle segment*, will be played only once.
- It is not possible to play non-contiguous segments when <u>RPT</u> field is set to 0x1, i.e., the *middle segment*, between the two non-contiguous segments will always be played.

6.7.3 Typical Operation Sequences

The following sections show different methods of launching a haptic waveform using RAM Playback mode.

Note that any previous waveform must have finished playing before programming RAM.

6.7.3.1 Triggered Start Sequence

The triggered start sequence is used to start playing a haptic waveform after programming the CONFIG.OE bit to 0x1.

The sequence is the following:

- 1. If not already done, set **CONFIG.OE** bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x2 to select RAM playback mode.
- 3. Write waveform data to RAM using <u>BURST RAM WRITE</u> command. See section 6.7.5 for a detailed example.
- 4. Write the RAM start and end addresses using RAM PLAYBACK WFS command.
- 5. Set <u>CONFIG.OE</u> bit to 0x1 when ready for haptic waveform playback.
- 6. The haptic waveform starts playing.
- 7. CONFIG.OE bit self-clears once the waveform is completed.

6.7.3.2 Immediate Start Sequence

The immediate start sequence is used to start a haptic waveform playback after issuing the RAM PLAYBACK WFS command. The sequence requires the CONFIG.OE bit to be set to 0x1 before issuing the RAM PLAYBACK WFS command.

Product Datasheet



The sequence is the following:

- 1. If not already done, set **CONFIG.OE** bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x2 to select RAM playback mode.
- 3. Set <u>CONFIG.OE</u> bit to 0x1 to enable output.
- 4. Write waveform data to RAM using <u>BURST RAM WRITE</u> command. See section 6.7.5 for a detailed example.
- 5. Write the RAM start and end addresses using RAM PLAYBACK command.
- 6. The haptic waveform starts playing.
- 7. <u>CONFIG.OE</u> bit is set to 0x0 once the waveform is completed.

6.7.3.3 Sensing Detection Sequence (BOS1921 Only)

The sequence is used to start haptic waveform playback when previously establish sensing detection conditions are met. The sequence requires the <u>CONFIG.AUTO</u>, <u>CONFIG.ONCOMP</u> and <u>CONFIG.SENSE</u> bits to be set to 0x1.

The sequence is the following:

- 1. If not already done, set CONFIG.OE bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x2 to select RAM playback mode.
- 3. Write waveform data to RAM using <u>BURST RAM WRITE</u> command. See section 6.7.5 for a detailed example.
- 4. Write the RAM start and end addresses using RAM PLAYBACK command.
- 5. Configure sensing detection condition as per section 6.4.3.
- 6. Set **CONFIG.OE** bit 0x1 to enable output.
- 7. The haptic waveform starts playing once sense detection conditions are met.



6.7.4 Waveform Example

Table 14 RAM PLAYBACK waveform examples

Table	Table 14 RAM PLAYBACK waveform examples				
#	RAM PLAYBACK COMMAND CONTENT	WAVEFORM PLAYBACK			
1	Reference waveform for further examples. RAM PLAYBACK command 1: - RPT = 0x0 - START ADDRESS[9:0] = 0x000 - REPEAT START ADDRESS[9:0] = 0x000 ¹ - END ADDRESS[9:0] = 0x3F0	Relative Amplitude 0x000 0x300 0x300 0x370 0x380 0x380 0x380			
2	RAM PLAYBACK command 1 (start): - RPT = 0x1 - START ADDRESS[9:0] = 0x080, - REPEAT START ADDRESS[9:0] = 0x080 - END ADDRESS[9:0] = 0x300 RAM PLAYBACK command 2 (stop): - RPT = 0x0 - START ADDRESS[9:0] = 0x000 ¹ - REPEAT START ADDRESS[9:0] = 0x000 ¹ - END ADDRESS[9:0] = 0x300	Relative Amplitude o Lime			
3	RAM PLAYBACK command 1 (start): - RPT = 0x1 - START ADDRESS[9:0] = 0x000 - REPEAT START ADDRESS[9:0] = 0x080 - END ADDRESS[9:0] = 0x300 RAM PLAYBACK command 2 (stop): - RPT = 0x0 - START ADDRESS[9:0] = 0x000 ¹ - REPEAT START ADDRESS[9:0] = 0x000 ¹ - END ADDRESS[9:0] = 0x370	Relative Amplitude o Lime			
4	RAM PLAYBACK command 1 (start): - RPT = 0x1 - START ADDRESS[9:0] = 0x000 - REPEAT START ADDRESS[9:0] = 0x080 - END ADDRESS[9:0] = 0x300 RAM PLAYBACK command 2: - RPT = 0x1 - START ADDRESS[9:0] = 0x000¹ - REPEAT START ADDRESS[9:0] = 0x370 - END ADDRESS[9:0] = 0x3F0 RAM PLAYBACK command 3 (stop): - RPT = 0x0 - START ADDRESS[9:0] = 0x000¹ - REPEAT START ADDRESS[9:0] = 0x000¹ - REPEAT START ADDRESS[9:0] = 0x000¹ - REPEAT START ADDRESS[9:0] = 0x000¹ - END ADDRESS[9:0] = 0x3F0	Relative Amplitude Time Time			



6.7.5 I²C Communication Example

In RAM Playback, waveform samples need to be first stored in the RAM to be fetched later. A typical RAM programming sequence is presented in Figure 21 which consist of programming a waveform using 10 samples to be played. The <u>OE</u> bit is set to 0x1 to start playing immediately after the <u>RAM Playback</u> command is issued.

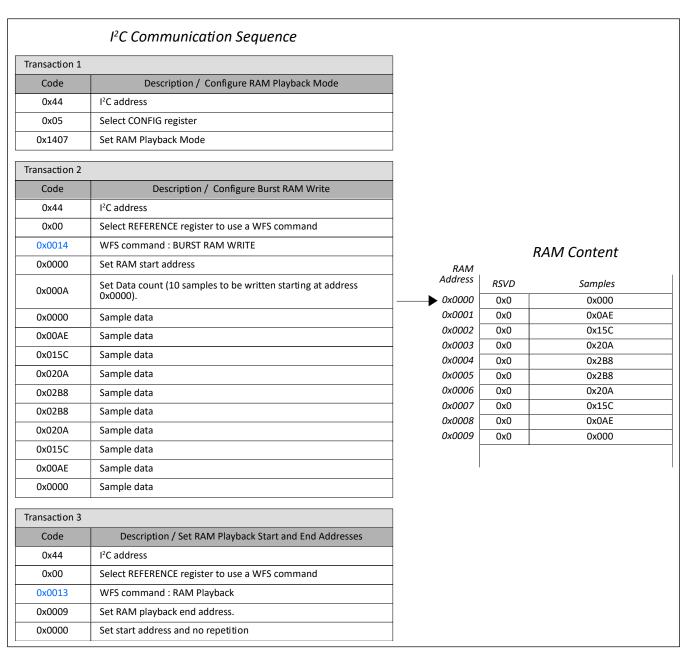


Figure 21: RAM Playback setup example

¹ The field is ignored.



6.8 RAM Synthesis Mode

In RAM Synthesis mode (<u>PLAY MODE[1:0]</u> bits set to 0x3), sine wave parameters stored by the user in RAM are used to generate simple to complex waveforms. Two types of information are stored in RAM:

- 1) SLICEs, written in the RAM using the <u>RAM ACCESS</u> command. Each SLICE contains a group of parameters used to produce a sine wave of defined amplitude, frequency, and number of cycles. It may also be ramped up and down (as shown in Figure 24). See section 6.8.1 for more details.
- 2) WAVEs, written in the RAM in predefined location using the <u>RAM ACCESS</u> command. A maximum of 15 WAVE blocks can be written in predefined RAM address. A WAVE defines a series of SLICEs to be played successively. All SLICEs of a WAVE must be written in order and contiguously in the RAM. See section 6.8.2 for more details.

A SEQUENCE is defined using the <u>RAM SYNTHESIS</u> command and point to 1 to 15 WAVE block RAM addresses to be played sequentially to create an output haptic waveform. See section 6.8.3 for more details.

A haptic waveform can be played by sending the desired START and END WAVE number using the <u>RAM SYNTHESIS</u> command. Once the waveform has been played, it can be played again by setting the START and END WAVE number again in the <u>RAM SYNTHESIS</u> command. The waveform will immediately start playing if the <u>RAM SYNTHESIS</u> command is issued while <u>OE</u> bit is set to 0x1.

No waveform should be playing while programming RAM using the <u>RAM ACCESS</u> command to avoid unexpected behaviour.

The WAVE and SLICE data are stored in RAM, as shown in Figure 22. WAVE must be located between RAM address 0x00 and 0x2C. SLICE blocks can be located at any free locations and arranged in any order, but they must not overlap.

Note that waveforms should begin and end with 0 V amplitude.

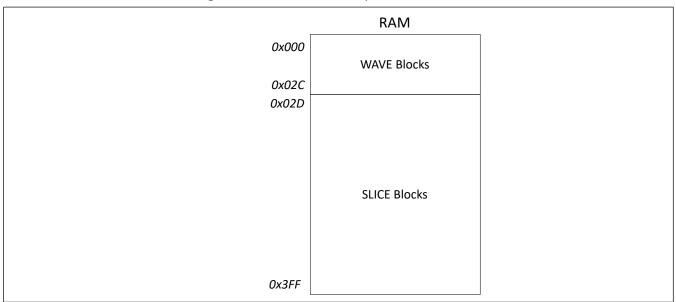


Figure 22: Representation of WAVE and SLICE blocks organized in RAM



6.8.1 SLICE Blocks

SLICE blocks in RAM contains the parameters used to synthesize sine waveforms. Each SLICE block contains three words grouping all parameters needed as described in Table 15. Figure 23 shows an example on how several SLICEs can be organized in RAM. Figure 24 illustrates an example of how these parameters shape a SLICE waveform. Many SLICES may be successively played to form more complex waveforms.

Note that <u>SLICE.MODE[1:0]</u> should be unipolar (set to 0x1 or 0x3) if <u>SLICE.AMPLITUDE[11:0]</u> is set to 0. *Table 15: SLICE block description*

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	NOT US	ED: 0x0						<i> </i>	MPLITU	•	•					
NO	T LICED.	0.0	CYCLES		FREQUENCY[7:0] [1:0] HCYC P180 SHAPEUP[3:0] SHAPEDN[3:								10.01			
WORD	T USED: BITS	NAME		IVIOD	E[1:0]	[1:0] HCYC P180 SHAPEUP[3:0] SHAPEDN[3:0] DESCRIPTION										
WORD	DITIO	147 (1412			Sets the voltage amplitude of the output waveform.											
1	11:0	AMPL	ITUDE		For bi outpu follow For ur	polar wa t peak-t	aveform o-peak v A vaveforr ak volta	s (<u>SLICE</u> voltage <i>MPLIT</i> ins (<u>SLIC</u> ge(Vour	.MODE[(V _{OUT-pkp} UDE[11 E.MODE	$\begin{bmatrix} 1:0 \end{bmatrix}$ set AMPLITU	to 0x0), MPLITU $\frac{095 \times I}{1}$ t to 0x1 JDE[11:	DE[11:0 / _{OUT-pk} 90 or 0x3), 0] is def] is defining $\frac{pk}{p}$, the relations as	ation be		
					This AMPLITUDE[11:0] value calculation is valid only for RAM Synthesis mode (PLAY MODE[1:0] bits set to 0x3). Note that the SLICE must be unipolar positive (SLICE.MODE[1:0] set to 0x1) if AMPLITUDE[11:0] is set to 0.											
2	15:8	CYCLE	CYCLES			Sets the number of times a full sine wave period is repeated, excluding SHAPEUP[3:0] & SHAPEDN[3:0] ramp times. The field is ignored if CONT is set to contain the total number of sine wave cycles played, CYCLETOTAL , (excluding rampand ramp-down) is defined by:										
					$CYCLE_{TOTAL} = CYCLES[7:0] + HCYC \times 0.5$ Note that CYCLE _{TOTAL} must be greater than 0.											
2	7:0	FREQUENCY			Defines the sine wave frequency. The waveform synthesizer has a frequency resolution of 3.9 Hz. FREQUENCY value must be greater than 0. The synthesized sine wave frequency (f_{OUT}) is defined by:											
3	12	CONT			$f_{OUT}[HZ] = 3.9 \times FREQUENCY$ Enables the SLICE repeat for continuous waveform playback. When enabled, the sine wave period is repeated until either a <u>STOP</u> or <u>NXTSL</u> bit is set to 0x1 is sen using the <u>RAM SYNTHESIS</u> command. 0x0: Continuous waveform playback disabled. 0x1: Continuous waveform playback enabled.											





15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
	NOT US	ED: 0x0							AMPLIT	JDE[11:0)]			•			
			CYCLE								REQUE	NCY[7:0)]				
	T USED:		CONT	MOD	E[1:0]	HCYC	P180		SHAPE	UP[3:0]			SHAPE	DN[3:0]			
WORD	BITS	NAME							DI	ESCRIPTION	NC						
3	11:10	MODE			Sets the waveform type. 0x0: Bipolar wave. 0x1: Unipolar & positive: In this mode, the amplitude of the waveform is half a bipolar waveform and shifted up by half the maximum amplitude of a bipolar waveform. 0x2: Reserved. 0x3: Unipolar & negative: In this mode, the amplitude of the waveform is half a bipolar waveform and shifted up by half the maximum amplitude of a bipolar waveform.												
3	9	НСҮС			When after a set to 0x0: D	Plays an additional half cycle at the end of the SLICE. When <u>CONT</u> is set to 0x1, an extra half cycle will be played at the end of the slice after a SLICE termination request has been made with either a <u>STOP</u> or <u>NXTSL</u> bit set to 0x1 using the <u>RAM SYNTHESIS</u> command. 0x0: Do not add half-cycle at the end of the waveform. 0x1: Add half-cycle at the end of the waveform.											
					Adds a 180° phase shift on the waveform.												
3	8	P180			0x0: No phase shift added. SLICE starts at min peak and increments. 0x1: A 180° phase shift is added. SLICE starts at max peak and decrements.												
3	7:4	SHAPE	UP[3:0]		SHAPEUP[3:0] sets the ramp-up time of the waveform from 0 V to V_{pk} .												
3	3:0	SHAPE	DN[3:0]		SHAPE are ad follow	EUP and dded to describe to see the se	SHAPED the total	ON dura	ation mu wavefor	ime of the state of the state of the green duration of the state of th	eater th on (<i>tsuc</i>	an the v_{E}), whic	vavefor h can be	m period e calcula	ted as		



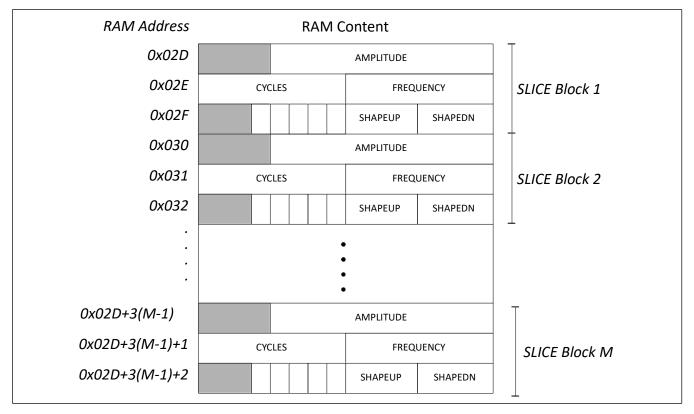


Figure 23: Sine wave SLICE parameters illustration

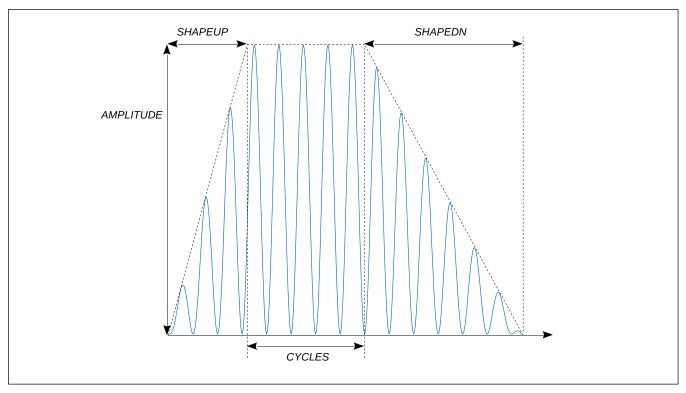


Figure 24: Sine wave SLICE parameters illustration

Product Datasheet



6.8.2 WAVE Blocks

A maximum of 15 WAVE blocks (numbered 0x0 to 0xE) can be written in RAM in fixed predefined location between RAM address 0x0000 and 0x002A as detailed in Table 17. Figure 25 presents how the WAVE blocks are organized in RAM.

A WAVE block in RAM contains three words and is described Table 16.

- 1. The SLICE START ADDRESS[11:0].
- 2. The SLICE END ADDRESS[11:0].
- 3. The WAVE COUNT[15:0].
- 4. SLICEs to be played sequentially must be placed in order and contiguously in RAM between the SLICE START ADDRESS[11:0] and the SLICE END ADDRESS[11:0].

Table 16: WAVE block description

						_	_	_	_			_	_				
15	14	13	12	11	10 9 8 7 6 5 4 3 2 1 0									0			
	NOT US	SED: 0x0			SLICE START ADDRESS[11:0]												
	NOT US	SED: 0x0			SLICE END ADDRESS[11:0]												
				•	COUNT[15:0]												
WORD	BITS	NAME			DESCRIPTION												
1	11:0	SLICE S ADDRE			Defines RAM address of the first word of the first SLICE to be fetched for waveform playback.												
2	11:0	SLICE E	ND ADD	RESS	Defines RAM address of the third word of the last SLICE to be fetched for waveform playback.												
						Sets the number of times the WAVE block is repeated from SLICE START ADDRESS[11:0] to SLICE END ADDRESS[11:0] for waveform playback.											
3	15:0	COUNT	-		If COUNT[15:0] is set to 0x0, the WAVE block will repeat indefinitely for continuous waveform playback until either a STOP or NXTW bit set to 0x1 is sent using the RAM SYNTHESIS command.												

Product Datasheet



Table 17: WAVE block number association with WAVE RAM ADDRESS.

WAVE BLOCK NUMBER	PREDEFINED WAVE RAM ADDRESS
0x0 ²	0x0000
0x1 ³	0x0003
0x2	0x0006
0x3	0x0009
0x4	0x000C
0x5	0x000F
0x6	0x0012
0x7	0x0015
0x8	0x0018
0x9	0x001B
0xA	0x001E
0xB	0x0021
0xC	0x0024
0xD	0x0027
0xE	0x002A

² WAVE block number 0x0 can be triggered using GPIO pin and KP.XTRIGR configuration bit.

³ WAVE block number 0x1 can be triggered using GPIO pin and KP.XTRIGE configuration bit.



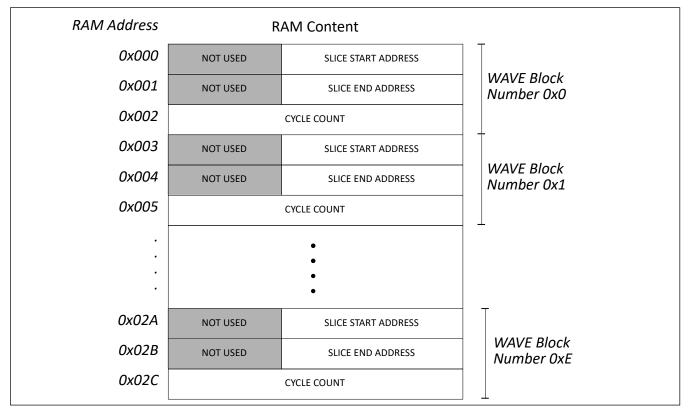


Figure 25: All 15 WAVE Blocks in RAM organized in RAM

6.8.3 SEQUENCE

A SEQUENCE is a haptic waveform to be played defined by the START and END WAVE number sent using the <u>RAM SYNTHESIS</u> command. For example, if <u>START WAVE[3:0]</u> is set to 0x3 and <u>END WAVE[3:0]</u> is set to 0x5, the waveform played will be composed of the WAVE blocks at RAM addresses 0x9, 0xC and 0xF, played sequentially.

The smallest sequence is when <u>START WAVE[3:0]</u> is equal to <u>END WAVE[3:0]</u> and thus only one WAVE block is played.

The largest waveform SEQUENCE to be played covers the 15 WAVE blocks, from WAVE number 0x0 to 0xE.

A SEQUENCE is repeated by issuing the RAM SYNTHESIS command with RPT field set to 0x1.

6.8.4 Continuous Waveform Playback

In RAM SYNTHESIS mode, any type of waveform segments (SEQUENCE, WAVE or SLICE) may be repeated indefinitely.

The Table 18 details how to start and stop the continuous waveform playback of any segment type.

A SEQUENCE that is being played continuously can be terminated by issuing a new <u>RAM SYNTHESIS</u> command with its field contents identical to the initial <u>RAM SYNTHESIS</u> command except with the <u>RPT</u> field set to 0x0.

A WAVE block being repeated continuously can be stopped by issuing a <u>RAM SYNTHESIS</u> command with the <u>NXTWV</u> field set to 0x1, which will instruct the WFS to play the next WAVE block of the SEQUENCE or end the waveform playback if the current WAVE block is the last one of the SEQUENCE. Similarly, a

Product Datasheet



SLICE block being repeated continuously can be stopped by issuing a <u>RAM SYNTHESIS</u> command with <u>NXTSL</u> field set to 0x1, which will instruct the WFS to play the next SLICE block or end the waveform if the current SLICE is the last SLICE of the SEQUENCE.

Using <u>RAM SYNTHESIS</u> command with <u>NXTSL</u> or <u>NXTWV</u> field set to 0x1 does not necessarily stop playback: any subsequent SLICE or WAVE block of the SEQUENCE will finish playing and may repeat indefinitely if configured that way.

Issuing a <u>RAM SYNTHESIS</u> command with <u>STOP</u> field set to 0x1 will play the next SLICE or WAVE block in the SEQUENCE only once, regardless of the state of <u>SLICE.CYCLES[7:0]</u>, <u>SLICE.CONT</u>, <u>WAVE.COUNT[15.0]</u> or <u>RAM SYNTHESIS.RPT</u> and thus preventing any of them of being repeated indefinitely. There are no options to force an immediate and sudden end of the haptic waveform playback.

Note the following:

- Issuing a <u>RAM SYNTHESIS</u> command with any of <u>NXTWV</u>, <u>NXTSL</u> or <u>STOP</u> field set to 0x1, stop the
 current SLICE or WAVE block being played even if it is not configured to play continuously. For
 instance, such a command could be used to put an early end to a long duration waveform.
- When a <u>RAM SYNTHESIS</u> command with any of <u>NXTWV</u>, <u>NXTSL</u> or <u>STOP</u> field set to 0x1 to stop a waveform of being played, the <u>START WAVE[3:0]</u> and <u>END WAVE[3:0]</u> fields must be set again.

Table 18: Summary of how to start and stop the continuous waveform playback.

SEGMENT TYPE	HOW TO START CONTINUOUS PLAYBACK	HOW TO STOP CONTINUOUS PLAYBACK
SEQUENCE	Issue an <u>RAM SYNTHESIS</u> command with <u>RPT</u> bit set to 0x1.	Issue an RAM SYNTHESIS command with RPT bit set to 0x0.
WAVE	WAVE.COUNT[15:0] is set to 0x0.	Issue an RAM SYNTHESIS command with NXTWV bit set to 0x1.
SLICE	SLICE.CONT is set to 0x1.	Issue an RAM SYNTHESIS command with NXTSL bit set to 0x1.

6.8.5 Typical Operation Sequences

The following sections show different methods of launching a haptic waveform using RAM Synthesis mode.

Note that any previous waveform must have finished playing before programming RAM.

6.8.5.1 Triggered Start Sequence

The triggered start sequence is used to start playing a haptic waveform after programming the <u>CONFIG.OE</u> bit to 0x1.

The sequence is the following:

- 1. If not already done, set <u>CONFIG.OE</u> bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x3 to select RAM synthesis mode.
- 3. Use <u>RAM ACCESS</u> WFS command to write WAVE and SLICE blocks in RAM. Multiple write sequences might be required, see section 6.8.7 for some examples.
- 4. Write START and END WAVE number to be played using RAM SYNTHESIS WFS command.
- 5. Set CONFIG.OE bit to 0x1 when ready for haptic waveform playback.
- 6. The haptic waveform starts playing.
- 7. CONFIG.OE bit is set to 0x0 once the waveform is completed.



6.8.5.2 GPIO Triggered Start Sequence

The GPIO triggered start sequence is used to start playing a haptic waveform using a GPIO falling edge signal and/or rising edge signal.

Note that <u>KP.XTRIGR</u> bit enables the GPIO rising edge triggering of WAVE block number 0x0 and <u>KP.XTRIGF</u> bit enables the GPIO falling edge triggering of WAVE block number 0x1.

The sequence is the following:

- 1. If not already done, set CONFIG.OE bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x3 to select RAM synthesis mode.
- 3. Use <u>RAM ACCESS</u> WFS command to write WAVE and SLICE blocks in RAM. Multiple write sequences might be required, see section 6.8.7 for some examples.
- 4. Write START and END WAVE number to be played using RAM SYNTHESIS WFS command.
- 5. Set **COMM.GPIODIR** to 0x1 to configure GPIO pin as an input.
- 6. Set KP.XTRIGR to 0x1 to enable rising edge triggering and/or set KP.XTRIGF bit to 0x1 to enable falling edge triggering.
- 7. Set CONFIG.OE bit to 0x1 when ready for haptic waveform playback.
- 8. The haptic waveform starts playing on GPIO signal.
- 9. CONFIG.OE bit is set to 0x0 once the waveform is completed.

6.8.5.3 Immediate Start Sequence

The immediate start sequence is used to start a haptic waveform playback after issuing the <u>RAM SYNTHESIS</u> WFS command. The sequence requires the <u>CONFIG.OE</u> bit to be set to 0x1 before issuing the <u>RAM SYNTHESIS</u> WFS command.

The sequence is the following:

- 1. If not already done, set CONFIG.OE bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x3 to select RAM synthesis mode.
- 3. Set **CONFIG.OE** bit to 0x1 to enable output.
- 4. Use <u>RAM ACCESS</u> WFS command to write WAVE and SLICE blocks in RAM. Multiple write sequences might be required, see section 6.8.7 for some examples.
- 5. Write START and END WAVE number to be played using RAM SYNTHESIS WFS command.
- 6. The haptic waveform starts playing.
- 7. CONFIG.OE bit is set to 0x0 once the waveform is completed.

6.8.5.4 Sensing Detection Sequence (BOS1921 Only)

The sequence is used to start haptic waveform playback when previously establish sensing detection conditions are met. The sequence requires the <u>CONFIG.AUTO</u>, <u>CONFIG.ONCOMP</u> and <u>CONFIG.SENSE</u> bits to be set to 0x1.

Product Datasheet



The sequence is the following:

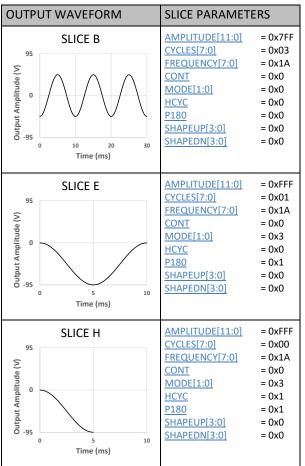
- 1. If not already done, set **CONFIG.OE** bit to 0x0.
- 2. Set CONFIG.PLAY MODE[1:0] bits to 0x3 to select RAM synthesis mode.
- 3. Use <u>RAM ACCESS</u> WFS command to write WAVE and SLICE blocks in RAM. Multiple write sequences might be required, see section 6.8.7 for some examples.
- 4. Write START and END WAVE number to be played using RAM SYNTHESIS WFS command.
- 5. Configure sensing detection condition as per section 6.4.3.
- 6. Set <u>CONFIG.OE</u> bit to 0x1 to enable output.
- 7. The haptic waveform starts playing once sense detection conditions are met.

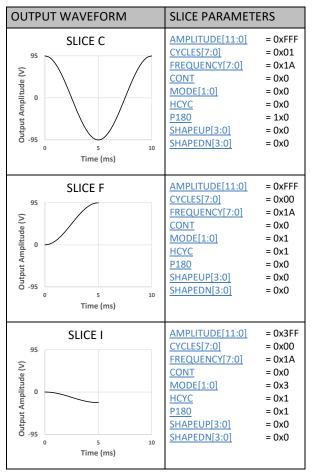


6.8.6 Waveform Examples

Table 19: SLICE waveforms examples

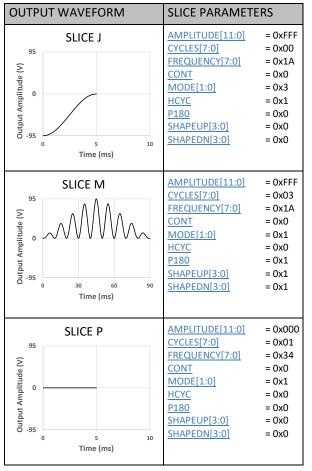
OUTPUT WAVEFORM	SLICE PARAMETERS
SLICE A 95 (x) 95 0 5 Time (ms)	AMPLITUDE[11:0] = 0xFFF CYCLES[7:0] = 0x01 FREQUENCY[7:0] = 0x1A CONT = 0x0 MODE[1:0] = 0x0 HCYC = 0x0 P180 = 0x0 SHAPEUP[3:0] = 0x0 SHAPEDN[3:0] = 0x0
SLICE D 95 (A) 95 (A) 95 (A) 95 (B) 10 (C)	AMPLITUDE[11:0] = 0xFFF CYCLES[7:0] = 0x01 FREQUENCY[7:0] = 0x1A CONT = 0x0 MODE[1:0] = 0x1 HCYC = 0x0 P180 = 0x0 SHAPEUP[3:0] = 0x0 SHAPEDN[3:0] = 0x0
SLICE G SLICE G SLICE G Time (ms)	AMPLITUDE[11:0] = 0xFFF CYCLES[7:0] = 0x00 FREQUENCY[7:0] = 0x1A CONT = 0x0 MODE[1:0] = 0x1 HCYC = 0x1 P180 = 0x1 SHAPEUP[3:0] = 0x0 SHAPEDN[3:0] = 0x0

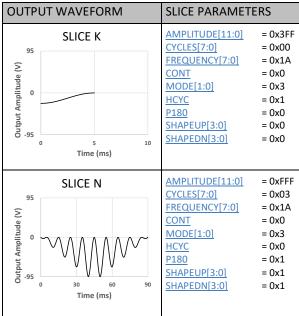




Product Datasheet







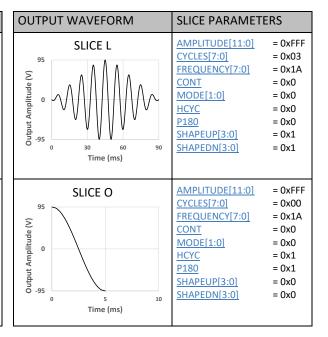




Table 20: Waveform examples built from a single WAVE block

WAVE BLOCK CONTENT	WAVEFORM
SLICEs: F + O + J WAVE.COUNT[15:0] = 0x1 RELOFF = 0x0 Note that waveform features a smooth start and stop for optimal integrity.	95 (A) epnt ymblitude (A) on the first of th
SLICEs: H + A + J WAVE.COUNT[15:0] = 0x1 RELOFF = 0x0 Note that SLICE A can be repeated to output a sinewave.	95 (x) apply from the following of the f
SLICE: D WAVE.COUNT[15:0] = 0x3 RELOFF = 0x0	95 (E) applitude Amplitude (N) 10 20 30 Time (ms)
SLICEs: F + O + J + P <u>WAVE.COUNT[15:0]</u> = 0x3 <u>RELOFF</u> = 0x0	95 Onthat Amplitude (V) 100 Output Amplitude (
SLICEs: I + B + K WAVE.COUNT[15:0] = 0x1 RELOFF = 0x1	95 (A) Pinnt Amplitude (A) Output Amplitude (A) Out

6.8.7 I²C Communication Examples

Figure 26 to Figure 29 give two examples showing how to program in RAM a waveform:

- Example 1 uses only 1 SLICE and 1 WAVE programmed with a single communication transaction.
- Example 2 uses 4 SLICEs and 3 WAVEs programmed with a communication transaction for each WFS command.



Both examples use <u>OE</u> bit set to 0x1 to start playing immediately after the <u>RAM SYNTHESIS</u> command is issued.

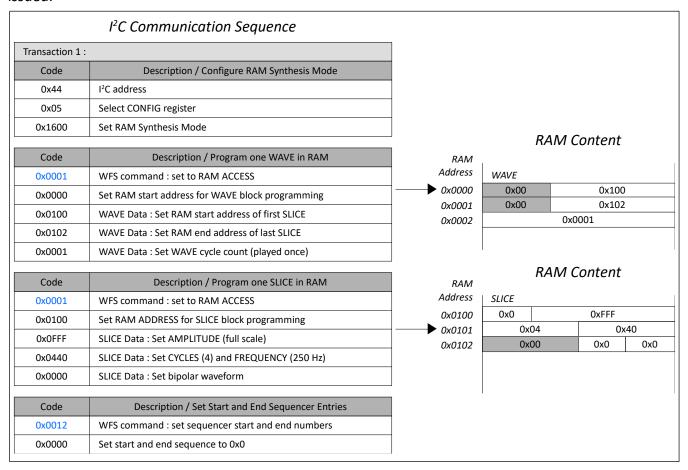


Figure 26: RAM synthesis mode setup example 1



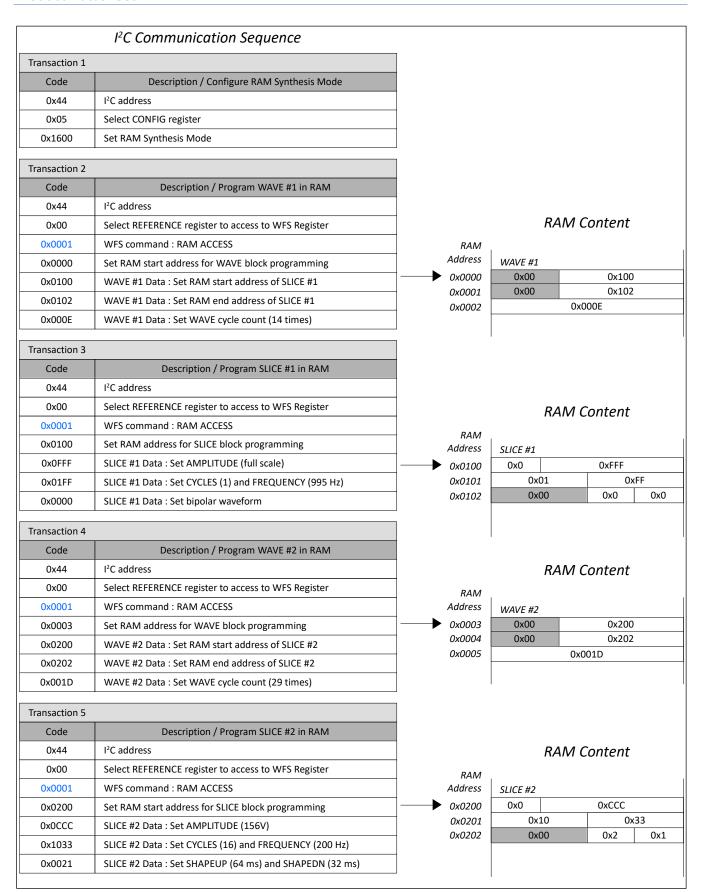


Figure 27: RAM synthesis mode setup example 2



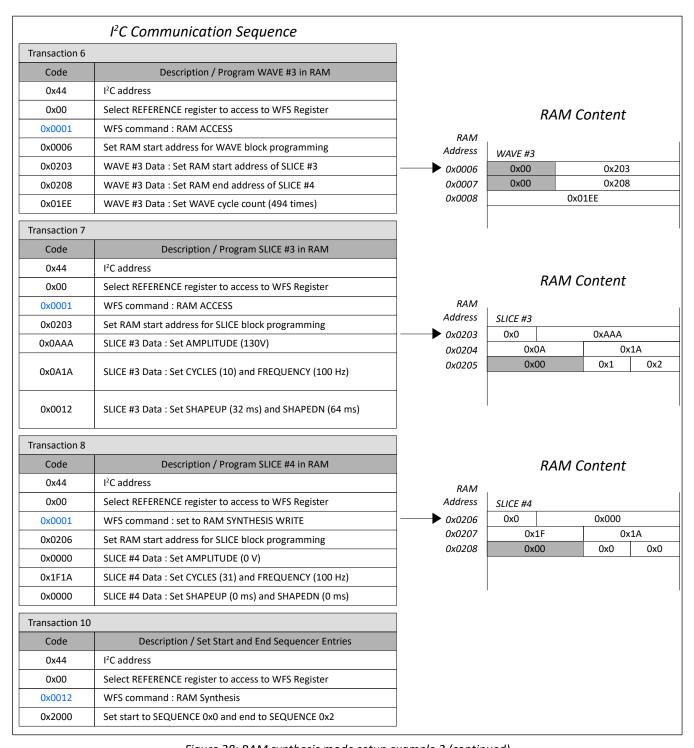


Figure 28: RAM synthesis mode setup example 2 (continued)



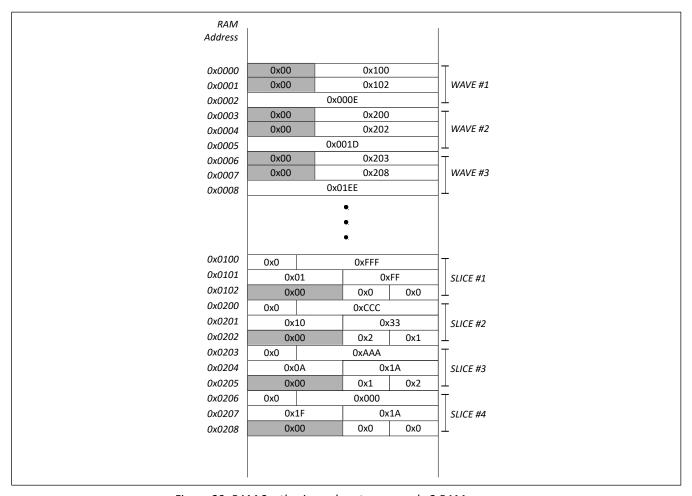


Figure 29: RAM Synthesis mode setup example 2 RAM summary



6.9 WFS Command Interpreter

The BOS1921/BOS1931 RAM is programmed using the WFS Command Interpreter accessible through REFERENCE register. WFS commands interpreter are used to store RAM Playback data and RAM Synthesis configuration data into RAM or to set FIFO DEPTH. WFS command list is summarized in Table 21, where word 0 is the command and the following words are the command payload.

Table 21 WFS commands list

COMMAND	WORD	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
RAM ACCESS	0		COMMAND[15:0] = 0x0001														
	1		R/W ADDRESS[9:0]														
	2		I	DATA1	[15:0]	: requi	red wh	en writ	e acce	ss is re	queste	ed by s	etting F	R/W bi	t to 0x0)	
	3		I	DATA2	[15:0]	: requii	red wh	en writ	e acce	ss is re	queste	ed by s	etting F	R/W bi	t to 0x0)	
	4		I	DATA3	[15:0]	: requi	red wh	en writ	e acce	ss is re	queste	ed by s	etting F	R/W bi	t to 0x0)	
FIFO DEPTH	0							соми	AND[1	5:0] =	0x0003	3					
	1														FIFO	DEPTH	[2:0]
RAM SYNTHESIS	0							соми	AND[1	5:0] =	0x001	2					
	1	EI	ND WA	VE[3:0	0]	S	TART W	/AVE[3	:0]				RELOFF	STOP	NXTW V	NXTSL	RPT
RAM PLAYBACK	0					1		COMN	AND[1	5:0] =	0x0013	3			1		
	1	RPT	9	START	ADDRI	ESS[4:0)]				EN	ID ADE	DRESS[9	9:0]			
	2		9	START	ADDRI	ESS[9:5	5]			F	REPEAT	STAR	T ADDR	ESS[9:	0]		
BURST RAM	0							COMM	AND[1	.5:0] =	0x001	4					
WRITE	1										STA	ART AD	DRESS[9:0]			
	2										D/	ATA CC	OUNT [9	9:0]			
	3		DATA1[15:0]														
	2+n		DATAn (n = DATA COUNT[9:0])														
FULL RAM READ	0		COMMAND[15:0] =0x0015														
FULL RAM READ	0		COMMAND[15:0] = 0xFF15														
BREAK																	

Figure 30 and Figure 31 present two different I²C communication sequence examples using either a single communication transaction for each WFS command or a single communication transaction to use several WFS commands. The first word of each WFS command is the command identifier. The number of following words to send depends on the command used.



Transaction 2	
Code	Description / WFS command 1
0x44	I ² C address
0x00	Select REFERENCE register to use a WFS command
0x0000	WFS command 1
0x0000	Expected word for command 1
Transaction 2	
Code	Description / WFS command 2
0x44	I ² C address
0x00	Select REFERENCE register to use a WFS command
0x0000	WFS comamnd 2
0x0000	Expected word for command 2
Transaction 3	3
Code	Description / WFS command 3
0x44	I ² C address
0x00	Select REFERENCE register to use a WFS command
0x0000	WFS command 3
0x0000	Expected word for command 3

Figure 30: Generic I²C communication sequence example to use a WFS command with a transaction

Transaction 1	•
Code	Description / WFS command 1
0x44	I ² C address
0x00	Select REFERENCE register to use a WFS command
0x0000	WFS command 1
0x0000	Write expected word for command 1
Code	Description / WFS command 2
0x0000	WFS command 2
0x0000	Write expected word for command 2
Code	Description / WFS command 3
0x0000	WFS command 3
0x0000	Write expected word for command 3

Figure 31: Generic l^2C communication sequence example to use several WFS commands with a single transaction



6.9.1 0x0001 RAM ACCESS

Table 22: RAM ACCESS details

	COMM	AND: 0x	(0001 RA	AM ACC	ESS												
Word	15	14	13	12	11	10	10 9 8 7 6 5 4 3 2 1 0										
0		COMMAND[15:0] = 0x0001															
1	NOT USED: 0x00 R/W ADDRESS [9:0]																
2		DATA1 [15:0]: required when write access is requested by setting R/W bit to 0x0															
3	DATA2 [15:0]: required when write access is requested by setting R/W bit to 0x0																
4				DATA3	[15:0]:	required	d when w	rite acce	ess is requ	uested b	y setting	R/W bit	to 0x0				
	WORI	D, BIT		NAME						DE	SCRIPTI	ON					
	Word 1, R/W 0: RAM Write Enable Bit [10] 1: RAM Read Enable																
	Word 2, ADDRESS Write/read start address within the RAM Bit [9:0]																

The RAM ACCESS command is used to either read a single location from RAM or writing a block of 3 words to RAM. In RAM Synthesis mode, a WAVE or SLICE block can be written to RAM with the following sequence (as described in Figure 32):

- 1. Set PLAY MODE[1:0] to 0x3 to select RAM Synthesis mode.
- 2. Write 0x0001 to the REFERENCE register to use the RAM ACCESS command
- 3. Write the following to the <u>REFERENCE</u> register:
 - a. Set R/W to 0x0 and set the ADDRESS [9:0] to the RAM start address.
 - b. Write the three words of either a WAVE or SLICE block to the <u>REFERENCE</u> register to store in RAM. See section 6.8 for details on the content of these words. The RAM address is automatically incremented between each word.

In either RAM Synthesis or RAM Playback, an RAM location can be read with the following sequence (as described in Figure 33):

- 1. Set <u>PLAY_MODE[1:0]</u> to 0x2 or 0x3 to select RAM Playback or RAM Synthesis mode.
- 2. Set RDADDR[4:0] to 0x1B to select RAM DATA reading.
- 3. Write 0x0001 to the REFERENCE register to use the RAM ACCESS command.
- 4. Write the following to the **REFERENCE** register:
 - a. R/W bit set to 0x1.
 - b. ADDRESS [9:0] bits set to the RAM address to read.
- 5. Read 2 bytes.



Transaction 1 : Set RAM Synthesis Mode								
Code	Description							
0x44+ W	I ² C address, write access							
0x05	Select CONFIG register							
0x2697	Set RAM Synthesis Mode							

Transaction 2	: Set the RAM SYNTHESIS WRITE register
Code	Description
0x44+ W	I ² C address
0x00	Select REFERENCE register to access to WFS Register
0x0001	WFS command : set to RAM SYNTHESIS WRITE
0x0063	Set RAM start address 0x063 for write access
0x0100	DATA 1
0x0102	DATA 2
0x000E	DATA 3

Figure 32: I²C communication sequence for RAM write using <u>RAM ACCESS</u> command

Transaction 1	: Set RAM Synthesis Mode											
Code Description												
0x44+ W	0x44+ W I ² C address, write access											
0x05	Select CONFIG register											
0x2697	0x2697 Set RAM Synthesis Mode											

Transaction 2	: Configure Broadcast												
Code													
0x44+ W	4+ W I ² C address, write access												
0x02	Select READ register												
0x002B Set bit BC for RAM_DATA reading													

Transaction 3	: Set the RAM SYNTHESIS WRITE register												
Code	Description												
0x44+ W	44+ W I ² C address, write access												
0x00	Select REFERENCE register to access to WFS Register												
0x0001	WFS command : set to RAM SYNTHESIS WRITE												
0x0463	Set RAM address 0x063 for read access												

Transaction 4	: Set the RAM SYNTHESIS WRITE register										
Code Description											
0x44+ R	I ² C address, read access										
0x0000 Read 2-byte											

Figure 33: RAM ACCESS sequence for RAM read

Product Datasheet



6.9.2 0x0003 FIFO DEPTH

Table 23: FIFO DEPTH details

	COMM	AND: 0	(0003 FI	FO DEPT	Ή											
ord/	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0							COM	/AND[1	L5:0] = C	x0003						
1						NOT	JSED: 0	k0000						FIFC	DEPTH	[2:0]
	WOR	WORD, BIT NAME DESCRIPTION														
	Word 1 Bit [2:0	,	FIFO D	EPTH		0x1: 5 0x2: 2 0x3: 1 0x4: 6	12 locat 56 locat 28 locat 4 locatio	ions ions ions ons	default) 4 locatic	ons. The	RAM ad	dress ra	nges are	e detaile	ed in Tal	ole 24.

The FIFO DEPTH command defines RAM locations to be used as a FIFO, used in FIFO mode. The RAM address ranges are detailed in Table 24.

By default, the FIFO depth corresponds to full 1024 RAM locations. Using a smaller FIFO allows preserving sections of RAM that could be used for RAM Synthesis or RAM Playback modes.

<u>PLAY_MODE</u> bits must first be set to RAM PLAYBACK or RAM SYNTHESIS mode (0x2 or 0x3) and <u>CONFIG.OE</u> bit must be set to 0x0 before issuing a FIFO DEPTH command.

Table 24: RAM address range used by FIFO according to FIFO DEPTH value

FIFO DEPTH[2:0]	NUMBER OF RAM	RAM ADDRESS RANGE FOR FIFO							
THO DEI III[2.0]	LOCATION	BEGIN	END						
0	1024	0x000	0x3FF						
1	512	0x200	0x3FF						
2	256	0x300	0x3FF						
3	128	0x380	0x3FF						
4	64	0x3C0	0x3FF						

6.9.3 0x0012 RAM SYNTHESIS

Table 25: RAM SYNTHESIS command details

		_																		
	COMM	AND: 0x	(0012 R/	AM SYN	THESIS															
Word	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
0		COMMAND[15:0] = 0x0012																		
1	END WAVE[3:0] START WAVE[3:0] NOT USED: 0x0 RELOFF STOP NXTWV NXTSL RPT														RPT					
	WOR	D, BIT		NAME		DESCRIPTION														
	Word 1 Bits [15	,	END W	/AVE					•			E), which y (see se	•		irst wor	d of				
	Word 1 Bits [11	,	START	WAVE					•			E), which y (see se	•		irst wor	d of				

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Product Datasheet



Word

	COMM	AND: 0	x0012 R	AM SYN	THESIS													
rd	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0			•	•		•	COMI	MAND[1	5:0] = 0	x0012				•				
1		END WA	AVE[3:0]		9	START W	/AVE[3:0	0]	NO	T USED:	0x0	RELOFF	STOP	NXTWV	NXTSL	RPT		
	WOR	D, BIT		NAME						DE	SCRIPT	ON						
	Word 1 Bit [3]	-,	RELOF	F		previo	ous SLICI ffset add ELOFF o	E. ded on t ption ca	he first i	SLICE is ed to ad	calculat d a DC (m match ed so th offset to	at it sta the wa	rts at 0V veform p	olayed.			
						wavef	orm mu	ıst be 0x		to ux1,	tne <u>SLI</u>	CE.MODI	E or eac	n SLICE I	OIOCKS O	rtne		
						Note the following:												
						Waveform will begin at 0 V amplitude.												
						Waveform should end with 0 V amplitude. The GUEST AND SUPPLY SHOULD BE A SUPPLY SHO												
						 The SLICE parameters <u>SHAPEUP[3:0]</u> and <u>SHAPEDN[3:0]</u> must be set to 0x0. 												
	Word 1 Bit [3]	٠,	STOP			Request to stop playing waveform by preventing SLICEs, WAVEs and SEQUENCE from being repeated (see section 6.8.2).												
						cycle)	of all th	e remai	ning SLI	CE or W	AVE blo	will play ock(s) of nd of the	the SEC	UENCE.	There a	re no		
								•	•		• .	layed wh g STOP t		ontinuo	usly or r	ot.		
	Word 1 Bit [2]	-,	NXTW	V								reaching eing play	•					
	Word 1 Bit [1]	-,	NXTSL			Plays the next SLICE of the SEQUENCE after reaching the end of the current SLICE. This option is used to stop a SLICE being played continuously.												
	Word 1 Bit [0]	-,	RPT			associ	ated wi		ND WA\	<u>/E[3:0]</u>	ias beei	initely. V n played, again.				ated		
	In RAM	Synthe	sis (hits	DI AV N	AODE[1	·Ol set to	2 Uv3) +	he devic	o nlave	all \Λ/Δ\/	F block	c startin	a from (START W	/Δ\/E[3·C	11 un		

In RAM Synthesis (bits <u>PLAY MODE[1:0]</u> set to 0x3), the device plays all WAVE blocks starting from <u>START WAVE[3:0]</u> up to <u>END WAVE[3:0]</u>, which is referred as the SEQUENCE.

Any write with the RAM SYNTHESIS command indicates that the waveform from <u>START WAVE[3:0]</u> up to <u>END WAVE[3:0]</u> is ready to be played. If <u>OE</u> bit is already set to 0x1, the waveform will start to play immediately after the RAM SYNTHESIS command is issued.

If the <u>AUTO</u> bit is set to 0x1, the waveform will be automatically played upon a sense voltage event. See section 6.4.3 for more detail.

The communication sequence to use the RAM SYNTHESIS command includes the following:

- 1. Write 0x0012 to REFERENCE register to use the RAM SYNTHESIS command.
- 2. Write the following word to <u>REFERENCE</u> register:
 - a. Bits 15:12 with END WAVE[3:0] (0x0 to 0xE).
 - b. Bits 11:8 with START WAVE[3:0] (0x0 to 0xE).
 - c. Bits 3:0 with STOP, NXTWV, NXTSL & RPT.

Note that the communication sequence assumes that bits PLAY MODE[1:0] are set to 0x3.



6.9.4 0x0013 RAM PLAYBACK

Table 26: RAM PLAYBACK command details

	COMM	AND: 0	k0013 R	AM PLA	YBACK													
Word	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0				•		•	COMN	/IAND[1	5:0] = 0>	(0013	•							
1	RPT		START	ADDRES	SS[4:0]					E	ND ADD	RESS[9:	0]					
2	0x0		START	ADDRES	SS[9:5]					REPEA	T START	ADDRE	SS[9:0]					
	WORE	D, BIT		NAME						DE	SCRIPTI	ON						
	Word 1 Bit [15]	•	RPT			next s REPEA the sa 0x1: V	Enables waveform repeat for continuous waveform playback. When enabled, the next sample after the sample fetched at END ADDRESS[9:0] is at <a address[9:0]"="" end="" href="REPEAT START ADDRESS[9:0]. When disabled, the waveform ends after fetching the sample at END ADDRESS[9:0] . 0x1: Waveform repeat enabled. 0x0: Waveform repeat disabled.											
	Word 1 Bits [14	•	START ADDRE	ESS[4:0]		5 LSBs	ne 10-bit (START T ADDRE	ADDRES	SS[4:0])	are sen	t in Wor	-	•	•	s where	the		
	Word 2 Bits [14		START ADDRE	ESS[9:5]			ART AD y in pro and.			_								
	Word 1 Bits [9:	•	END A	DDRESS		corres	Sets the 10-bit RAM end address for fetching RAM Playback samples, which corresponds to the address of the last sample to be played before the playback ends (if RPT bit is set to 0x0) or before the playback is repeated (if RPT bit is set to 0x1).											
	Word 2, REPEAT START Sets the 10-bit RAM repeat start address for fetching RAM Playback samples who Bits [9:0] ADDRESS RPT bit is set to 0x1. The field is ignored if RPT bit is set to 0x0.												when					

The <u>START</u> and <u>END ADDRESS[9:0]</u> entered with the RAM PLAYBACK command indicate the location in RAM of the samples to be fetched for waveform playback when the RAM Playback is initiated.

The waveform segment between <u>REPEAT START ADDRESS[9:0]</u> and <u>END ADDRESS[9:0]</u> is repeated when setting <u>RPT</u> to 0x1. To end a waveform playback repetition, a new RAM PLAYBACK command must be issued with <u>RPT</u> set to 0x0 with the <u>END ADDRESS</u> equals to or greater than the initial <u>END ADDRESS[9:0]</u>.

The 16-bit samples in RAM use the same format as for Direct Mode (see section 6.5) and FIFO mode (see section 6.6) and includes the bits [11:0] as the waveform amplitude, see REFERENCE[11:0] bits description.

The samples in RAM are written using **BURST RAM WRITE** command.

The use of the RAM PLAYBACK command indicates that the waveform is ready to be played. Thus, if <u>OE</u> bit is set 0x1, the waveform will start to play when issuing a RAM Playback command.

The communication sequence to program the <u>START ADDRESS[9:0]</u> and <u>END ADDRESS[9:0]</u> using the RAM PLAYBACK command includes the following:

- 1. Write waveform data in RAM using **BURST RAM WRITE** command.
- 2. Write 0x0013 to the <u>REFERENCE</u> register to use the RAM PLAYBACK command.
- 3. Write word 1 to the REFERENCE register.
- 4. Write word 2 to the <u>REFERENCE</u> register.

Note that the communication sequence assumes that bits PLAY MODE[1:0] are set to 0x2.



6.9.5 0x0014 BURST RAM WRITE

Table 27: BURST RAM WRITE command details

	COMM	AND: 0	k0014 Bl	URST RA	M WRI	TE											
Word	15	14	13	12	11	10	9	8	7	6	5	4	3	2		1	0
0		•	•	•		•	COMN	/IAND[1	5:0] = 0x	0014					•		
1		ı	NOT USE	D: 0x00						STA	ART ADD	RESS [9	9:0]				
2		ſ	NOT USE	D: 0x00						D	ATA CO	UNT [9:	0]				
3							•	DATA	[15:0]								
	WOR	WORD, BIT NAME DESCRIPTION Word 1 START ADDRESS Defines the 10-bit address from where to start writing in the RAM with the															
	Word 1, Bits [9:0] Defines the 10-bit address from where to start writing in the RAM with the following constraint: 0 ≤ START ADDRESS ≤ 1023																
	Word 2 Bits [9:	•	DATA (COUNT		constr DATA	COUNT	has a m	aximum	value o	f 1023.	en on t	he RAM	with t	he	follov	ring
	Word 3 Bits [15	-	DATA			Define	COUNT es data t ENCE[11	o be wr	tten in t			he sam	e forma	t as th	e		

The BURST RAM WRITE command is used to write multiple words to the RAM when using RAM Playback mode (PLAY MODE[1:0] set to 0x2). The data format uses the same format as the REFERENCE[11:0] bits.

The communication sequence to write to RAM using the BURST RAM WRITE WFS command includes the following:

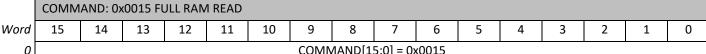
- 1. Write 0x0014 to the <u>REFERENCE</u> register to use the BURST RAM WRITE command.
- 2. Write the RAM <u>START ADDRESS</u> word to the <u>REFERENCE</u> register.
- 3. Write the <u>DATA COUNT</u> word to the <u>REFERENCE</u> register.
- 4. Write the number of REFERENCE[15:0] words equal to DATA COUNT. RAM write address is incremented automatically between words.

Note that the communication sequence assumes that PLAY MODE[1:0] bits are set to 0x2.



6.9.6 0x0015 FULL RAM READ

Table 28: FULL RAM READ command details



COMMAND[15:0] = 0x0015

In RAM Synthesis or RAM Playback mode (PLAY MODE[1:0] set to 0x2 or 0x3), the FULL RAM READ command is used to read the full RAM content on the communication interface. The device will stay in this mode until all the 1024 RAM addresses have been read or until the FULL RAM READ BREAK command is used.

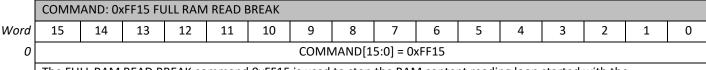
The communication sequence to use the FULL RAM READ command includes the following:

- Set bits RDADDR[4:0] to 0x1B to select RAM DATA reading.
- 2. Write 0x0015 to REFERENCE register to use the FULL RAM READ command.
- 3. Write 0x0000 (or any value except 0xFF15) to REFERENCE register.
- 4. Read 2 bytes
- Repeat step 3) and 4) until the last RAM address or until using the FULL RAM READ BREAK command. The RAM address is automatically incremented.

Note that the communication sequence requires that PLAY MODE[1:0] bits are set to 0x2 or 0x3.

6.9.7 0xFF15 FULL RAM READ BREAK

Table 29: FULL RAM READ BREAK command



The FULL RAM READ BREAK command 0xFF15 is used to stop the RAM content reading loop started with the FULL RAM READ command.



6.10 Register Map

Table 30: Main register map

ADDR.	NAME	DEFAULT VALUE	TYPE ⁴	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x00	REFERENCE	0x0000	RW								DATA	[15:0]							
0x01	ION_BL	0x03A0	RW		RS	VD		FSWM	AX[1:0]	SB[1:0]				I_ON_SC	ALE[7:0]			
0x02	<u>DEADTIME</u>	0x046A	RW		RS	VD					DHS[6:0]	•					DLS[4:0]		
0x03	<u>KP</u>	0x0080	RW		RSVD		XTRIGF	XTRIGR						KP[10:0]	•				
0x04	KPA KI	0x02A0	RW		RS	VD			KIBAS	E[3:0]					KPA	[7:0]			
0x05	CONFIG	0x1000	RW	ONCOMP ⁽¹⁾	AUTO ⁽¹⁾	SENSE ⁽¹⁾	GAINS ⁽¹⁾	GAIND	PLAY_M	ODE[1:0]	RET	SYNC	RST	POL_SENS ⁽¹⁾	OE	DS		PLAY_SRATE	
0x06	PARCAP	0x003A	RW	1		RSVD		CCM UPI RSVD PAR								CAP			
0x07	SUP RISE	0x4967	RW		I2C_AD	DR[3:0]		LP			VDD[4:0]					TI_RIS	E[5:0]		
0x08	INT ENABLE	0x0000	RW					RSVD	,				IE_FHE	IE_STCHG	IE_MXERR	IE_SENSF(1)	IE_PLAY	IE_MAXP	IE_ERR
0x09	SENSING ⁽¹⁾	0x0000	RW	SIGN		REP[2:0]							STHRES	SH[11:0]					
0x0A	TRIM	0x0000	RW	TRIMR	W[1:0]		RS	VD					TRIM_OSC				Т	RIM_REG[2:0]
0x0B	COMM	0x001E	RW		RSVD		RDAI	STR	OD		GPIOSEL[2:0]]	GPIODIR	TOUT		I	RDADDR[4:0]	
0x10	IC STATUS	0x0001	RO			RS	SVD			STAT	E[1:0]	OVV	OVT	MXPWR	IDAC	UVLO	SC	FULL	PLAYST
0x11	FIFO_STATE	0x4400	RO		RSVD		ERROR	FULL	EMPTY					FIFO_SP	ACE[9:0]				
0x18	SENSE VALUE(1)	0x06CF	RO	POL_SENS	SENSE	GAIN	SENS_FLAG	FLAG SENSE_VALUE[11:0]											
0x1B	RAM DATA	0x0000	RO								RAM_DA	TA[15:0]							
0x1E	CHIP ID	0x3781 ⁽¹⁾	RO		CHIP_F	EV[3:0]	_						CHIP_I	D[11:0]					
0x1F	INT STATUS	0x0000	RO					RSVD IS_FHE IS_STCHG IS_MXERR IS_SENSF IS_PLAY IS_MAXP IS									IS_ERR		

(1) BOS1921 only.

⁴ RO are read-only registers. RW are read/write registers.



6.10.1 0x00 REFERENCE

Table 31: REFERENCE register details

ADDRI	ESS: 0x0	0	REFER	ENCE		DEFAL	JLT: 0x0	000							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RS	VD						F	REFEREN	NCE[11:0)]				
							REFEREN	NCE[15:0)]						
BITS	NAME			DEFAL	JLT	TYPE	DESCR	IPTION							
11:0	REFER			0x000		RW	define compl waveful determine the intermine device REFER ±95 V set to	orm: shi nined by Ampli REFERE Eernal Al defined ENCE[11 when G 0x1.	sired ar ormat ft data I v: tude[V] ENCE is DC inpu I by GAI L:0] mus	mplitude The dev left to al $\begin{bmatrix} p_k \\ p_k \end{bmatrix} = \frac{R}{m}$ REFEREI t range a ND. st be set	e of the ice will vign MSE $EFERE$ 2^{11} — NCE[11: and FB_{rc} is between x0, and	output i work wi 3s. The a (NCE) 1 × 0] decin atio is the en 0x93 output :	in 12-bit th a low amplitude $V_{ref} \times D_{ref}$ and value feedba 1 and 0x ±13.3 V	t two's rer-resol de in volume FB_{ratio} e, $V_{ref} = \frac{1}{3}$ eck ratio when $\frac{1}{3}$	3.6 is of the output AIND is
15:0	REFER	ENCE		0x000	0	RW	0x2 or		efines th	ne Wave	form Sy			DE[1:0]) comma	

6.10.2 0x01 ION_BL

Table 32: ION_BL register details

ADDRI	ESS: 0x0	1	ION_B	L		DEFAU	LT: 0x03	3A0							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RS	VD		FSWM	AX[1:0]	SB[:	1:0]			I	_ON_SC	CALE[7:0]		
BITS	NAME			DEFAL	JLT	TYPE	DESCR	IPTION							
11:10	FSWM	IAX		0x0		RW	0x0: 1 0x1: 8: 0x2: 6: 0x3: 5:	33 kHz 66 kHz				hing fre	quency.		
9:8	SB			0x3		RW	0x0: 33 0x1: 44 0x2: 53 0x3: 63	4 ns 3 ns				pplicatio	ons.		

Product Datasheet



ADDRI	ESS: 0x0)1	ION_B	L		DEFAU	LT: 0x03	3A0							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RS	SVD		FSWM	AX[1:0]	SB[:	1:0]			I	_ON_SC	CALE[7:0]		
BITS	NAME			DEFAL	ILT	TYPE	DESCR	IPTION							
7:0	I_ON_	SCALE		0xA0		RW	switch I_OI Where	. I_ON_! V_ <i>SCAL</i>	SCALE[7 <i>E</i> [7: 0] y = 50 n	[:0] is denoted $= rou$ s and FE	etermine $nd\left(\frac{La}{L_1}\right)$	turn or turn or ted by: $\frac{tency}{\times 2^{-12}}$ The feedby	\times R_{sense}	$\times FB_{ro}$	utio)

6.10.3 0x02 DEADTIME

Table 33: DEADTIME register details

ADDRI	ESS: 0x0	12	DEADT	IME		DEFAU	LT: 0x04	16A							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
RSVD				DHS[6	:0]	•	•				DLS[4:	0]			
BITS	NAME			DEFAL	ILT	TYPE	DESCR	IPTION							
11:5	DHS			0x23		RW	High-S	ide (HS)	switch t_{dea} oe adjus	turns or $_{d-HS}=$ ted usin	DHS [6:	(LS) swifts, as period (LS) swifts, as perio	r: 1 <i>ns</i> relatior	s off and	d the
							conne capaci	cting SW	he para / pin to nd & PC	sitic cap L ₁ . C _{sw} i B metal	acitance s influer trace co	e measu nced by onnected	red on the para		е
4:0	DLS			0x0A		RW		ne delay de (LS) :	switch t	urn on (t _{dead-LS}),	-		n off and	d the
							for mo	-		-		ns minim n be adj		l should r	work



6.10.4 0x03 KP

Table 34: KP register details

ADDR	ESS: 0x0	3	KP			DEFAU	ILT: 0x00	080							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RSVD		XTRIGF	XTRIGR						KP[10:0]]				
BITS	NAME			DEFAU	ILT	TYPE	DESCR	IPTION							
12	XTRIG	F		0x0		RW	Table: (PLAY GPIOD the GF 0x1: Fa	tes wave 17) on G MODE[<u>MR</u> must PIO exten alling ed alling ed	PIO falli 1:0] bits be set t rnal trigg ge exter	ing edge s set to (to 0x1 to ger fund rnal trig	e using F Dx3). D set the ctionality ger activ	RAM Syr e GPIO a y. vated or	ithesis s an inp		
11	XTRIG	R		0x0		RW	Table: (PLAY GPIOD the GF 0x1: R	tes wave 17) with MODE[PIR must PIO extensising edgising edgis	GPIO ri 1:0] bits be set t rnal trigg ge exter	sing edg s set to (to 0x1 to ger fund nal trigg	ge using Dx3). It is set the stionality ger actives.	RAM Sy e GPIO a y. ated on	nthesis s an inp	·	
10:0	КР			0x080		RW		ne physio rtional g	ain, whi	ich is de	termine	_		controll	er

6.10.5 0x04 KPA_KI

Table 35: KPA_KI register details

ADDR	ESS: 0x0	4	KPA_K	I		DEFAU	LT: 0x02	2A0							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RS	VD			KIBAS	E[3:0]					KPA	[7:0]			
BITS	NAME			DEFAL	JLT	TYPE	DESCR	IPTION							
11:8								nines th is deter	mined b	y:		the interpretation $\frac{1024}{2^{KIBASE}}$	egrated	PI contr	oller,
7:0	КРА			0xA0		RW	contro	ller, whi	ich is ca $KPc = I$	KP + 2	by: × KPA	× AMPI	LITUDE	ntegrate 11:0] de	



6.10.6 0x05 CONFIG

Table 36: CONFIG register details

	ESS: 0x0	5	CONFI			DEFAU	ILT: 0x10	000							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ONCOMP	AUTO	SENSE	GAINS	GAIND	PLA MODI	_	RET	SYNC	RST	POL_ SENSE	OE	DS	PLA'	Y_SRATE	[2:0]
BITS	NAME			DEFAU	LT	TYPE	DESCR	IPTION				•			
15	ONCO (BOS1	MP 921 only	()	0x0		RW	the th SENS compa 0x1: A 0x0: Ir ONCO	reshold FLAG to arator. ctive nactive MP need	defined 0x1. <u>SE</u> ds to be	by <u>STHF</u> NSE nee	RESH[11 ds to be	e set to to clear	automa 0x1 to u	atically so use the s	et ensing er a
14	AUTO (BOS1	921 only	/)	0x0		RW	This fe section 0x1: E 0x0: D The All played	eature no n 6.4.3 f nable isable JTO bit i	eeds <u>ON</u> or more is cleare ITO bit	ed wavef NCOMP a e detail c ed auton back to (ered aut	and <u>SEN</u> on for A natically 0x1 to e	ISE set to utomation	o 0x1. S c Haption	ee c Playbad form is	ck.
13	SENSE BOS19	921 only)	0x0		RW	imped with <u>S</u> 0x1: E 0x0: D Note t - <u>PLAY</u> - <u>ONC</u> if SENS	ance to ENSE V nable isable the follow ST bit m OMP, SIG	read th ALUE[1: wing: ust be (GN & Al set to 0	Ox1 befo UTO bits	re settii and <u>SE</u>	r voltage ng SENS <u>NSING</u> r	e that ca E bit to egister	ox1.	effect
12	GAINS (BOS1	921 Onl	y)	0x1		RW	(<i>FB</i> _{ratio} 0x0: <u>S</u>). ENSE_VA	<u> </u>	ution by L:0] LSB i L:0] LSB i	s set to	54.5 m	V & FBra	_{ntio} is set	to 31
11	GAIND			0x0		RW	feedba 0x0: <i>V</i> 0x1: <i>V</i>	ack loop _{ουτ} rang _{ουτ} rang	(FB _{ratio}) e set to e set to	±95 V & ±13.28	FB _{ratio} s	set to 31	L	n of the	
10:9	PLAY_	MODE		0x0		RW	0x0: D 0x1: F 0x2: R	irect mo IFO mod AM Play	ode (see le (see s back m	playbace section section 6 ode (see node (see	6.5) .6) section	า 6.7)			

Product Datasheet



ADDRE	ESS: 0x0	5	CONFI	G		DEFAU	ILT: 0x1	000							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ONCOMP	AUTO	SENSE	GAINS	GAIND	PLA MOD	_	RET	SYNC	RST	POL_ SENSE	OE	DS	PLA	SRATE	[2:0]
BITS	NAME			DEFAU	LT	TYPE	DESCR	IPTION							
8	RET			0x0		RW	SLEEP 0x0: R	mode (<u>[</u> egisters	os set to and RA	a retenti o 0x1). M data r M data r	etentio	n is ena	bled	M when	using
7	SYNC			0x0		RW	Activa 0x1: E 0x0: D	nable	i-chip s	ynchroni	ization.				
6	RST			0x0		RW	defaul reset i Make Direct 0x1: D	t values s compl	and go eted. EERENC mode. ftware		E mode	. RST bit	t self-cle	ears onc	e the
5	POL_S (BOS19	ENSE 921 Onl	у)	0x0		RW	sensin 0x1: O	g (<u>SENSI</u> UT+ pin	bit is s is conn	f the OU set to 0x ected to ected to	1). VDD	Γ- pins w	hen the	e device	is
4	OE			0x0		RW	(BOS1 0x1: E 0x0: D OE bit	921 only nable isable will clea	r). er autor	orm play natically et to 0x2	at the ϵ	end of a			
3	DS			0x0		RW	Sets th	ne powe pit <u>OE</u> is DLE	r mode	when th			playing	wavefo	rm
2:0	PLAY_	SRATE		0x0		RW	Direct, 0x0, 0: 0x0: 1: 0x1: 5 0x2: 2:	FIFO or x1 or 0x: 024 ksps 12 ksps 56 ksps 28 ksps 4 ksps 2 ksps 6 ksps	RAM P 2), as fo	te used layback illows:			•		



6.10.7 0x06 PARCAP

Table 37: PARCAP register details

ADDRI	ESS: 0x0	6	PARCA	ΛP		DEFAU	ILT: 0x00	D3A							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		RSVD			CCM	UPI	RSVD				PARCA	AP[7:0]			
BITS	NAME			DEFAU	ILT	TYPE	DESCR	IPTION							
10	ССМ			0x0		RW	to ope mode the de 0x0: D 0x1: Both tis retailed the de Using	rate the (CCM) ovice ope CM mod OS1921, commer sign has	e buck-bor discor erates o de only /BOS193 nded to s a value ode allov	oost continuous nly in Do	overter conduction CM modes es betwo bit to to H.	in contiliction mode. de. veen DC 0x1 only	nuous co ode (DCI M or CC when t	ose whe onduction of the onduction of the onduction of the one of	on erwise, e e etor in
9	UPI			0x0		RW	Enable 0x0: D 0x1: E		nidirect	onal Po	wer Inp	ut.			
7:0	PARCA	AΡ		0x3A		RW	Where connections	e C _{SW} is to cting SW tance ar and FB _r	4 <i>RCAP</i> he para / pin to nd & PC	[7: 0] = sitic cap L ₁ . C _{SW} i B metal	$\frac{\sqrt{\frac{C_{SW}}{L_1}}}{2^{-11}}$ acitance influent ace contains	nced by onnected	ired on the para d on SW	the node	I PCB



6.10.8 0x07 SUP_RISE

Table 38: SUP_RISE register details

ADDRI	ESS: 0x0	7	SUP_R	ISE		DEFAU	ILT: 0x49	967							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	I2C_AD	DR[3:0]		LP		'	VDD[4:0]]				TI_RIS	SE[5:0]		
BITS	NAME			DEFAU	LT	TYPE	DESCR	IPTION							
15:12	I2C_A	DDR		0x4		RW			s of the , I2C_AD	_		static ad	ddress, i	.e., I ² C	
									3C 4-bit see Tab		e ID (i.e	., bits [1	5:12] of	the	
									C_ADDI			_	only if <u>G</u>	PIODIR	is set
							to 0x1	and is	[3:0] va preserve he state	ed wher	the de	-		-	
								e of 0x0 DDR[3:0	is returi] value.	ned on a	a read, ı	egardle	ss of th	e	
11	LP			0x1		RW			power v or most		•	IDLE mo	de. Def	ault val	ue
									w powe						
10:6	VDD			0x05		RW	Repres by:	ents th	e supply	voltage	seen a	t RP/VD	D pin ar	nd is de	fined
									VDI	D[4: 0]	$=\frac{\left(\frac{V_{DD}}{0.0}\right)}{1}$	$\frac{[V]}{26}$) $-\frac{1}{2}$	128		
									31, use 0, use (
5:0	TI_RIS	E		0x27		RW	Sets th	e propo	rtional (gain for	the offs	et dete	rmined	by:	
									TI _{RISE} [5	$[5:0] = \frac{7}{3}$	$\frac{T_{CLK} \times 3}{L_1}$	31.25 ——×	$\frac{FB_{ratio}}{R_{sense}}$	<u>-</u>	
								TCLK = d by <u>GA</u>	70 ns an <u>IND</u> .	d <i>FB_{ratio}</i>	is the f	eedback	ratio o	f the de	evice



6.10.9 0x08 INT_ENABLE

Table 39: INT_ENABLE register details

ADDR	ESS: 0x0	8	INT_E	NABLE		DEFAL	JLT: 0x0	000							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				RSVD					IE_FHE	IE_ STCHG	IE_ MXERR	IE_ SENSF	IE_ PLAY	IE_ MAXP	IE_ERR
BITS	NAME			DEFAL	JLT	TYPE	DESCF	RIPTION							
6	IE_FHI			0x0		RW	In FIFO when 1: inte	es the FID mode the FIFC errupt is errupt is	(<u>PLAY_N</u>) is at lea enabled	<u>//ODE[1</u> ast half I	: <u>0]</u> set t	t. o 0x1), t	he inter	rupt trig	ggers
5	IE_STO	CHG		0x0		RW	The in STATE 1: inte	terrupt [1:0] charrupt is	triggers anges. enabled	when tl	-	ot. ce state i	ndicate	d by	
4	IE_MX	ERR		0x0		RW	The in wavef occurs capac	orm pla	triggers yed on t he outp d is too enabled	when the output he output haptingh.	ut and t	i differei the setp form is t	oint, wh	ich typi	cally
3	IE_SEN	NSF		0x0		RW	The in sectio	-	triggers enabled	when a	-	ot. /oltage [Event is	detecte	d (see
2	IE_PLA	ΛY		0x0		RW	The in		triggers enablec	when <u>P</u> I		nterrupt. s set to (
1	IE_MA	XP		0x0		RW	The in and M	es Max F terrupt IXPWR is errupt is errupt is	triggers s set to (enabled	when n Ox1. I		n amour	nt of pov	wer is us	sed
0	IE_ER	?		0x0		RW	The in STATE 1: inte	es Error terrupt [1:0] is serrupt is errupt is	triggers set to 0x enabled	when tl 3.		ce is in e	rror stat	e and	



6.10.10 0x09 SENSING (BOS1921 Only)

Table 40: SENSING register details

ADDRI	ESS: 0x0	9	SENSII	NG		DEFAU	JLT: 0x0	000							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SIGN	ı	REP[2:0]				•	•	•	STHRES	H[11:0]			•		
BITS	NAME			DEFAL	LT	TYPE	DESCR	RIPTION							
15	SIGN			0x0		RW	thresh	iold (<u>STF</u> <u>OMP</u> mu elow	HRESH[1	<u>1:0]</u>) to	genera			below t ge event	
14:12	REP			0x0		RW	STHRE] to gen		_			e or belo NCOMP	
11:0	STHRE	SH		0x000		RW	genera The ar Where feedba is a 12	ate a ser mplitude V _{ref} = 3 ack ratio -bit sign SAINS se Maxio corre Minir	ase volta $V = \frac{STP}{V}$ $V = \frac{STP}$	age ever olts is d HRESH 2^{11} — ne interidevice d ber. ,, the followable g to 13.	etermin [11: 0] 1 nal ADC defined llowing STHRES 28 V STHRES	ned by: $ imes V_{ref} imes Cinput ra$	ust be s $\langle FB_{rati} \rangle$ ange, FE S and S oply: value is	et to 0x1 Sratio is th THRESH[S 0x6CF,	e

Product Datasheet



6.10.11 0x0A TRIM

Table 41: TRIM register details

ADDRESS: 0x0A TRIM						DEFAU	FAULT: 0x0000									
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
TRIMRW[1:0] RS			VD		TRIM_OSC[6:0] TRIM_REG[2:0]							2:0]				
BITS	S NAME			DEFAULT		TYPE	DESCRIPTION									
15:14	TRIMRW			0x0 RW			Trim control bits for adjusting the internal clock oscillator frequency (TRIM_OSC[6:0]) and 1.8 V internal regulator voltage (TRIM_REG[2:0]), see Figure 34. Hardware fuses values vary from chip-to-chip. More detail is available in the section 6.2.14. TRIMRW[1:0] bits are automatically reset to 0x0 after each operation. 0x0: Default behaviour where Hardware fuses are latched to the Trim Block at power-up 0x1: Resets the Trim Block with the Hardware Fuses and then transfers Trim Block data to TRIM_OSC[6:0] & TRIM_REG[2:0] for reading (wait for 1 ms before reading) 0x2: Transfers Trim Block data to TRIM_OSC[6:0] & TRIM_REG[2:0] for reading (wait for 1 ms before reading) 0x3: Writes TRIM_OSC[6:0] & TRIM_REG[2:0] to Trim Block and transfers back Trim Block data to TRIM_OSC[6:0] & TRIM_REG[2:0] for reading (wait for 1 ms before reading)									
2:0	TRIM_			0x00		RW	approx Maxim Minim Excess malfur The in compl	ximately num frec um frec ive char nction. I ternal 1 ement.	v 150 kH quency a quency a nge in os This is ar .8 V reg	z. at 0x1F. at 0x20. scillator advana ulator (F	frequer ced feat REG pin	ncy may ure.) trimmin mately 2	induce o	circuit	5	
									age at 0							



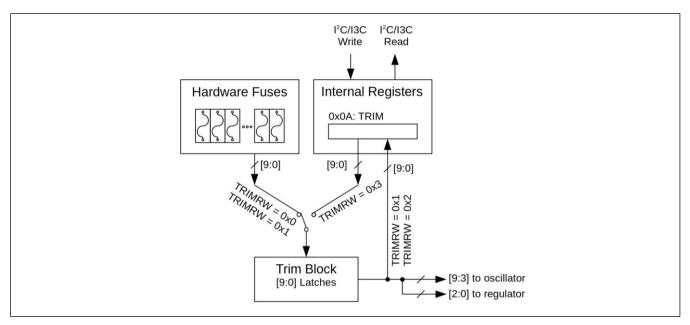


Figure 34: Trim control block diagram

6.10.12 0x0B COMM

Table 42: COMM register details (BOS1921)

ADDRI	ESS: 0x0	В	COMN	1		DEFAU	LT: 0x00	D1E							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RSVD		RDAI	STR	OD	GP	IOSEL[2	:0]	GPIODIR	TOUT		RD	ADDR[4	:0]	
BITS	NAME			DEFAU	ILT	TYPE	DESCR	IPTION							
12	RDAI			0x0		RW	operat 0x0: <u>R</u> 0x1: <u>R</u>	tion. <u>DADDR[</u> <u>DADDR[</u>	uto-incr 4:0] bits 4:0] bits 0] bits ar	are not increm	t modifi ent afte	ed er a regis	ster read	d	
11	STR			0x0		RW	comm only th 0x1: A 0x0: N Regard registe	unicatione address and address address the address the addreser) will n	natic incom. Allowess of the auto-incomes auto-es STR bit not autor	e first re e first re rement increme value, a maticall	g severagister (egister (every twent ent an addra y incren	al conse see Figu vo bytes ess of Ox nent to a	cutive rore 20).	egisters ERENCE	using
10	OD			0x0		RW	0x0: O	ne GPIO pen-Dra ush-Pull		type.					

Product Datasheet



ADDRE	ESS: 0x0E	3	COMN	1		DEFAU	LT: 0x00	1E							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RSVD		RDAI	STR	OD	GP	IOSEL[2:0	0]	GPIODIR	TOUT		R	DADDR[4	1:0]	
BITS	NAME			DEFAU	ILT	TYPE	DESCRI	PTION							
9:7	GPIOSE	L		0x0		RW				signal th	nat is o	utput o	n the GP	IO pin v	when
									t to 0x0.						
									eset Stat e device		et nroc	ess			
									reset sta		or p. o c				
							1: Devi	e is no	ot in rese	et state a	and is r	eady fo	r operati	ion	
							0x1: W:	evefori	m Playba	ick Stati	ıs				
									state of						
							0: PLAY								
							1: PLAY	ST bit	is 0x0						
							0x2: Err	or Sta	te						
										is in err	or state	e (<u>STAT</u>	<u>E[1:0]</u> se	t to 0x3	3):
							0: Error 1: No e								
							1.100	TOT GC	iteeteu						
							0x3: Ma								
									aximum : oower, d		-	ver is us	sed (state	e of MX	<u>(PWR</u>):
								-	power is		-				
							0x4: FIF	-	(PLAY M	10DF[1:	∩l set t	n ()x1)	indicates	s if the	FIFO is
									FULL bit		<u>oj</u> set t	.O OX1),	maicate.	, ii tiic	0 .5
							0: FIFO								
							1: FIFO	is not	full						
							0x5: Int	errupt							
										interrup	ots of II	NT STA	TUS regis	ster is 0)x1:
							0: Inter		ending ot pendin	ıσ					
							2011		e periori	.0					
							0x6: Se							- dia:	- (-+-:
							of <u>SENS</u>			a met tl	ne dete	ection tr	igger co	naitions	s (state
								_	ction cor	ndition r	net				
							1: Sens	e dete	ction cor	ndition r	ot met	:			
							0x7: FIF	O Half	Fmntv						
										10DE[1:	<u>0]</u> set t	o 0x1),	indicates	s if the	FIFO is
							at least								
									f of the F alf of the						
6	GPIODI	R		0x0		RW			tion of th			aie dV	anabit		
	31 1001			0.00					n output		۲				
							0x0: GP		-	•					
<u> </u>	l					l	1								

Product Datasheet



ADDRI	ESS: 0x0	В	COMM	1		DEFAU	LT: 0x00	D1E							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RSVD		RDAI	STR	OD	GP	IOSEL[2	:0]	GPIODIR	TOUT		RD	ADDR[4	:0]	
BITS	NAME			DEFAU	ILT	TYPE	DESCR	IPTION							
5	TOUT			0x0		RW	it fails playba The co 0x1: Ei 0x0: D Note t	to received. Indition: Wave (PLA) The control The finable isable hat PLA	eout med ve the n s for the eform pland (MODE output is PLAYST b	ecessar timeou ayback I [1:0] bit enabled it has b	y data s t are th mode is ts set to d (<u>OE</u> bi een 0x1	e follow either F 0x0 or 0 t set to for at le	during v ing: EIFO or E 0x1). 0x1).	vavefori Direct m	ode
4:0	RDADI	OR		0x1E		RW	comm	unicatio	e interna on bus du CHIP_ID	uring a r	ead.			ırned or	the

6.10.13 0x10 IC_STATUS

Table 43: IC_STATUS register details

ADDR	ESS: 0x1	0	IC_STA	ATUS		DEFAU	LT: 0x0	001							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		RS	VD			STAT	E[1:0]	OVV	OVT	MXPWR	IDAC	UVLO	SC	FULL	PLAYST
BITS	NAME			DEFAL	JLT	TYPE	DESCR	IPTION							
9:8 STATE Ox0 RO Indicates the state of the device. STATE[1:0] = 0x3 indicates that one of the following errors occurred: OVV, OVT, IDAC, UVLO or SC. Ox0: IDLE Ox1: CALIBRATION Ox2: RUN. Ox3: ERROR OVV Ox0 RO Overvoltage fault bit. The voltage level that triggers the fault															
7	OVV			0x0		RO	depen trigger trigger 0x1: 0	ds on <u>G</u> red at 10 red at 14	AIND va 00 V and 1 V and oltage e	alue. If <u>G</u> d above. above. axceeded	AIND is If GAIN	set to 0: D is set	x0, the f to 0x1, t	ault is the fault	is
6	OVT			0x0		RO	0x1: O	-	perature	lt bit. e detecto ure is Ol		ne device	е		
5	MXPW	/R		0x0		RO	Indica 0x1: N	tes that Iaximun	R _{sense} re n power	ning bit. eached tl r, distort unt of po	ne maxi ion likel		owed cı	urrent.	

Product Datasheet



ADDRI	ESS: 0x1	0	IC_STA	ATUS		DEFAU	LT: 0x00	001							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	•	RS	VD	•		STAT	E[1:0]	OVV	OVT	MXPWR	IDAC	UVLO	SC	FULL	PLAYST
BITS	NAME			DEFAU	ILT	TYPE	DESCR	IPTION							
4	IDAC			0x0		RO	IDAC s	tatus bi	t.						
							0x0: N A prob	o proble lem wit	em with	rrent det current OAC mos	detecti		s that Rs	sense or L	ı is
							To rec	nected. over fro CONFIG.		AC erroi	r, a soft	ware res	set mus	t be dor	ie
3	UVLO			0x0		RO	V _{DD} Un	der-vol	tage fau	ılt bit.					
									_	e detect sh enoug		e trying	to outp	ut a wa	/eform
2	SC			0x0		RO	Piezo l	oad sho	rt circu	it fault b	it.				
										ected on detected	the pie	zo load			
1	FULL			0x0		RO				full whe	en using	g FIFO m	ode		
										to 0x1).					
							_	FO is ful FO is no							
0	PLAYS	Γ		0x1		RO		-	-	nulti-fun	ction st	atus bit.	. Its fund	ction de	pends
								AY MOD			4 01 .		D. 41/07		
								ect mode new dat		MODE[:	1:0] set	to 0x0),	PLAYSI	bit indi	cates
								sample r							
							1: Nex	t sample	e requir	ed					
							when	FIFO is e	mpty:	MODE[1:	<u>0]</u> set to	o 0x1), F	PLAYST b	oit indica	ates
) is not ϵ) is emp							
							In RAN 0x2 or finishe 0: Wav	۱ Synthe	esis or F AYST b g: s not do	RAM play it indicat					



6.10.14 0x11 FIFO_STATE

Table 44: FIFO_STATE register details

ADDRI	ESS: 0x1	1	FIFO_S	TATE		DEFAU	LT: 0x44	100							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	RSVD		ERROR	FULL	EMPTY					FIFO_SP	ACE[9:0]			
BITS	NAME			DEFAL	JLT	TYPE	DESCR	IPTION							
12	ERROR	ł.		0x0		RO	any of <u>SC</u> . 0x1: A	the follo	owing fa	e is in err aults has occurre	occurr	-		-	II.
11	FULL			0x0		RO	Same	as <u>FULL</u>	bit.						
10	EMPTY	/		0x1		RO	Same	as <u>PLAY</u>	T bit.						
9:0	FIFO_S	SPACE		0x000		RO	When FIFO_S free sp	FIFO De SPACE va	pth is s alue of (ailable (of free s et to 102 0x000 in (if <u>EMPT</u> 0x0).	24 (using dicates	g <u>FIFO D</u> that eitl	DEPTH co her ther	ommano e are 10	l), a 24

6.10.15 0x18 SENSE_VALUE (BOS1921 Only)

Table 45: SENSE_VALUE register details

ADDRI	ESS: 0x1	8	SENSE	_VALUE		DEFAU	LT: 0x0	6CF							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
POL_ SENSE	SENSE	GAIN	SENS_ FLAG					SE	NSE_VA	LUE[11	:0]				
BITS	NAME			DEFAU	ILT	TYPE	DESCR	RIPTION							
15	POL_S	ENSE		0x0		RO	(<u>SENS</u>) 0x1: 0	tes the p E is set t OUT+ pin OUT- pin	o 0x1). is conn	ected to	V _{DD}	/hen usi	ng sensi	ng mode	
14	SENSE			0x0		RO	If the SENSE Ox0: T	tes if the value is VALUE he devic he devic	not 0x1, [<u>11:0]</u> b e is not	then th its shou in sensi	ne <u>SENS</u> Id be ig ng mod	FLAG a nored.		s set to (0x1).
13	GAIN			0x0		RO	norma device	of the fee al operat e is in sei sponds to	ion, this	s value o ode (<u>SEI</u>	correspo	onds to	GAINS b	it when	the
12	SENS_	FLAG		0x0		RO	thresh 0x1: si	ndicating nold in se ignal abo lothing c	ense mo ove/belo	de. To r ow thres	eset th				

Product Datasheet



ADDRI	ESS: 0x1	8	SENSE	_VALUE		DEFAU	LT: 0x06	5CF							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
POL_ SENSE	SENSE	GAIN	SENS_ FLAG					SE	NSE_VA	LUE[11	:0]				
BITS	NAME			DEFAULT TYPE DESCRIPTION											
11:0	SENSE	_VALUE		0x6CF		RO	is defin	ned by: nplitud e V _{ref} = 3	<i>le[V] =</i> .6 V is tl	SENSE	'_ <i>VALU</i> 2 ¹¹ — 1 nal ADC	Signal. The signal $E[11:0]$ input race of $\frac{GAIN!}{GAIN!}$	$ V_{ref} $ ange and	$\times FB_{ra}$	tio

6.10.16 0x1B RAM_DATA

Table 46: RAM_DATA register details

ADDRI	ESS: 0x1	В	RAM_I	DATA		DEFAU	LT: 0x00	000							
15	14	13 12 11 1				9	8	7	6	5	4	3	2	1	0
						F	RAM_DA	TA[15:0]						
BITS	NAME			DEFAL	JLT	TYPE	DESCR	IPTION							
15:0	RAM_	DATA		N/A		RO			read fro ND or RA				-		

6.10.17 0x1E CHIP_ID

Table 47: CHIP_ID register details

ADDRI	ESS: 0x1	E	CHIP_I	D		DEFAU	LT: 0x37	781 (BOS	51921),	0x378B	(BOS19	31)			
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	CHIP_R	EV[3:0]							CHIP_II	D[11:0]					
BITS	NAME			DEFAU	ILT	TYPE	DESCR	IPTION							
15:12	CHIP_I	REV		0x3		RO	0x3: Re 0x2: Re	es the cevision [evision (evision () C	sion.					
11:0	CHIP_I	D		0x781		RO	0x781:	es the c BOS192 BOS193	21						



6.10.18 0x1F INT_STATUS

Table 48: INT_STATUS register details

ADDRI	ESS: 0x1	F	INT_S	TATUS		DEFAL	JLT: 0x00	000							
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				RSVD					IS_ FHE	IS_ STCHG	IS_ MXERR	IS_ SENSF	IS_ PLAY	IS_ MAXP	IS_ ERR
BITS	NAME			DEFAU	LT	TYPE	DESCR	IPTION							
6	IS_FHE	<u> </u>		0x0		RO	In FIFO when t 1: inte	mode	(<u>PLAY N</u>) is at le active	MODE[1 ast half	:0] set to	ared on o 0x1), t		rupt trig	gers
5	IS_STC														
4	0: interrupt is not active										cally				
3	IS_SEN	ISF		0x0		RO	Sense The interior	Trigger terrupt	Interrup triggers ons and active	ot Status when so I <u>SENS</u> F	ensed d	ed on rea ata mee set to 0x	t the de	tection	
2	IS_PLA	·Υ		0x0		RO	The int	terrupt is	triggers active	when P		Cleared s set to C		i.	
1	IS_MA	XP		0x0	0: interrupt is not active RO Max Power Interrupt Status. Cleared on read. The interrupt triggers when maximum amount of power is used and MXPWR is set to 0x1. 1: interrupt is active 0: interrupt is not active										
0	IS_ERF	R		0x0		RO	The int STATE 1: inter		triggers set to 0x active	when th		on read. e is in e	rror stat	e and	



7 Implementation

This section presents the following different BOS1921/BOS1931 configurations:

- Typical configuration, using <u>UPI</u> bit set to 0x0.
- UPI configuration, using <u>UPI</u> bit set to 0x1.
- Differential output configuration, driving a bipolar voltage on a single piezo actuator.
- Single-ended output configuration, driving a unipolar voltage on 2 piezo actuators.

Note that shorting the VBUS pin with the RP/VDD pin in the typical configuration is not mandatory but allows for better power efficiency.

7.1 Differential Output Configuration

Differential output configuration is required for applications using both sensing and driving capabilities. In this configuration, piezoelectric actuator is driven with one terminal connected to OUT+ pin and the other terminal connected to OUT- pin. This configuration can achieve a differential output voltage of $190 \ V_{pk-pk}$.

Typical application schematics of the differential output configuration are shown in Figure 35 and Figure 36, without and with Unidirectional Power Input (UPI) configuration. The BOM list is detailed in Table 49.

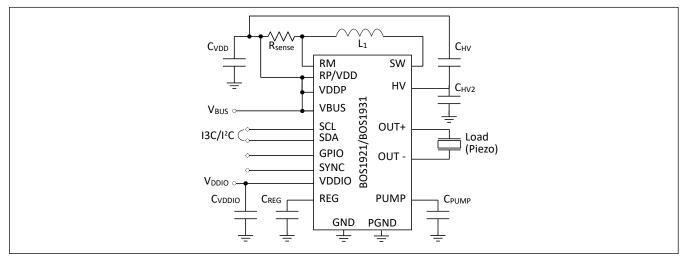


Figure 35: Schematic using differential output and typical configuration (UPI bit set to 0x0)



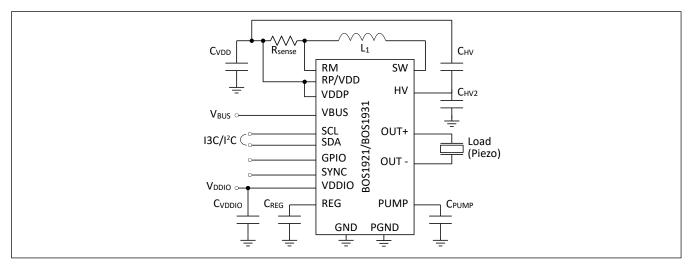


Figure 36: Schematic using differential output and UPI configuration (UPI bit set to 0x1)

7.2 Single-Ended Configuration

When sensing is not needed (BOS1921 and BOS1931), the single-ended output configuration allows driving two actuators independently to reduce the bill-of-material, see Figure 37. With this configuration, the piezo actuators positive terminal must be connected respectively to OUT+ and OUT- while both actuators negative terminals are connected to VDD.

This configuration can output up to 95 V waveform with positive polarity on each actuator. A bipolar waveform must be programmed to output a waveform on 2 actuators. The positive programmed voltage will output on Load 1 while the negative programmed voltage will output on Load 2.

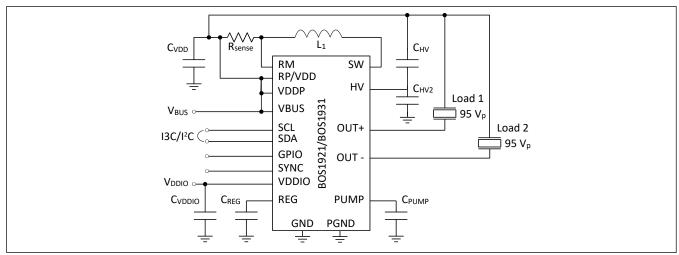


Figure 37: Typical schematic with single-ended output configuration (UPI bit set to 0x0)

7.3 External Components

Typical values of external components are presented in Table 49. See section 7.5 and application notes for details on selecting components.

Product Datasheet



Table 49: Recommended external components for 190 V_{pk-pk}/100 nF load

COMPONENT	DESCRIPTION	TYPICAL VALUE FOR MAXMUM LOAD	TYPICAL VALUE FOR 10 nF LOAD
CL	Load capacitance	100 nF	10 nF
CVDD	V _{DD} capacitor	10 μF (<u>UPI</u> bit set to 0x0) 100 μF (<u>UPI</u> bit set to 0x1)	10 μF
Creg	REG pin capacitor	100 nF	
СРИМР	PUMP pin capacitor		
CVDDIO	V _{DDIO} decoupling capacitor		
Сни	Capacitor on HV pin to VBUS	10 nF	1 nF
Снv2 ⁵	Capacitor on HV pin to GND	3.9 nF	1.5 nF
Rsense	Current sense resistor	0.2 Ω	1 Ω
L ₁	Boost inductor	10 μΗ	68 μH

7.4 Initialization

7.4.1 Power-Up Sequence

- 1. Apply power to the BOS1921/BOS1931 device with the following criteria:
 - a. The V_{BUS} voltage must ramp-up at a minimum rate of 1 V/ms .
 - b. The V_{DDIO} pin must be powered up after the V_{BUS} pin or at the same time.
- 2. Wait for 3 ms during which the BOS1921/BOS1931 starts-up with the following sequence:
 - a. Power-up
 - b. Initialization
 - c. Going to SLEEP mode.

As shown in Figure 38, V_{BUS} , GPIO & REG pin voltage can be monitored to assess device initialisation.

- 3. Wake-up from SLEEP by writing on the $I^2C/I3C$ bus (see section 6.3.2.1 for I^2C and 6.3.2.2 for I3C).
- 4. Wait 50 μs for the BOS1921/BOS1931 to reach IDLE mode.
- 5. Program the desired internal registers according to your application.
- 6. BOS1921/BOS1931 is ready for waveform playback.

⁵C_{HV2} is recommended for reduction of high frequency noise.



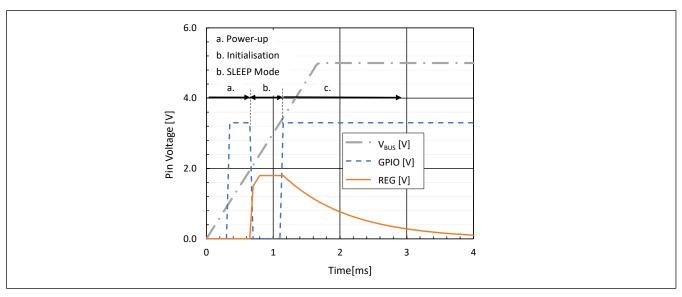


Figure 38: Typical V_{BUS}, GPIO & REG pin voltage during initialisation

7.4.2 Start-Up Sequence

After the initial power-up sequence, the following start-up sequence applies:

- From SLEEP mode, one must perform steps 3 to 6 of the section 7.4.1.
- From IDLE mode, BOS1921/BOS1931 is ready for waveform playback.

7.5 Design Methodology: selection of component

7.5.1 Load Selection

The BOS1921/BOS1931 is designed to drive a capacitive load impedance (Z_L) of up to 5.3 k Ω at 190 V_{pk-pk}, which gives 100 nF at 300 Hz. Larger load capacitances can be driven if the waveform amplitude is reduced (see Figure 14). The conditions must be selected so as not to exceed the maximum peak transient current at SW pin (I_{SW}) of 1.3 A, which is limited by R_{sense} (see section 7.5.3 for R_{sense} selection).

You can use the following procedure to estimate I_{SW} using the desired conditions (I_{SW} could be higher in practice):

- 1. Set the output signal maximum frequency (f_{OUT}). e.g., 200 Hz.
- 2. Set the maximum amplitude of the waveform (V_{pk}) . e.g., 95 V for a 190 V_{pk-pk} output.
- 3. Set the minimum supply voltage (V_{BUS}) value during operation. e.g., 3 V.
- 4. Calculate the Isw and ensure it does not exceed 1.3 A:

Bipolar Waveform

Unipolar Waveform

$$V_{\text{out}} = V_{\text{pk}} \sin(45^{\circ}) + V_{\text{BUS}}$$
 $V_{\text{out}} = \frac{V_{\text{pk}}}{2} (1 + \sin(30^{\circ})) + V_{\text{BUS}}$ (1)

$$\overline{I_{\text{out}}} = 2\pi f_{OUT} C_L V_{\text{pk}} \cos(45^\circ) \qquad \overline{I_{\text{out}}} = \pi f_{OUT} C_L V_{\text{pk}} \cos(30^\circ) \qquad (2)$$



5. Calculate the average input current using:

$$\overline{I_{in}} = 1.5 \times \frac{\overline{I_{out}} \times V_{out}}{V_{BUS}}$$
(3)

6. Calculate the inductor peak current (current at SW pin):

$$I_{SW} = C \times \overline{I_{in}} \tag{4}$$

With C equals to 2 if only DCM mode is used (\underline{CCM} bit set to 0x0) or equals to 1.5 if CCM or DCM mode is used (\underline{CCM} bit set to 0x1).

7.5.2 C_{HV} Selection

Load capacitance (C_L) defines the required value of component C_{HV} (up to 10 nF):

$$C_{HV} = 5\% C_{L} \tag{5}$$

The C_{HV} capacitor should have a voltage rating of at least the peak output waveform amplitude. A C_{HV} capacitor with a minimum voltage rating of 95 V is required to output the full-scale output voltage.

7.5.3 Rsense Selection

The value of R_{sense} must enable a current range appropriate for the I_{SW} value calculated in equation (4). R_{sense} value is determined using equation (6). The current limit of the power converter is set by R_{sense} components.

$$R_{\text{sense}} \le \frac{0.256 \,[\text{V}]}{I_{\text{sw}}} \tag{6}$$

$$Current limit = \frac{0.256 [V]}{R_{sense}}$$
 (7)

7.5.4 L₁ Selection

The BOS1921/BOS1931 can use any COTS inductor. An L_1 inductor greater than 10 μ F is recommended but the inductance can be chosen to optimize the power / size / performance trade-off according to the user application as follows:

- Select lower inductance together with a higher switching frequency using <u>FSWMAX[1:0]</u> bits to optimize distortion (i.e., THD+N).
- Select larger inductance to reduce the switching frequency. In general, lower switching frequency corresponds to lower power consumption.



A f_{swmin} value of 300 kHz is recommended.

Use the following procedure to select the first inductor value and then experiment with other values to optimize your application if required:

1. Calculate the ideal duty ratio of the power converter stage:

$$D = 1 - \frac{V_{BUS}}{V_{BUS} + V_{pk}} \tag{8}$$

2. Calculate the maximum L₁ inductor value:

$$L_1 \le \frac{V_{\text{BUS}}D}{I_{\text{pk}}f_{\text{swmin}}} \tag{9}$$

Select an L_1 inductor with a saturation current higher than I_{SW} and higher than the current limit determined in equation (7).

7.5.5 Input Capacitor (CVDD)

An input capacitor (C_{VDD}) must be placed next to the inductor because of the current requirement of the power converter. A low-ESR capacitor of at least 10 μ F is recommended.

If the Unidirectional Power Input mode is enabled (<u>UPI</u> bit set to 0x1), the energy recovered from the load in buck conversion accumulates on the C_{VDD} . Energy accumulation on C_{VDD} causes the input voltage to increase. The voltage increase must not make the total voltage on C_{VDD} exceed the maximum absolute 5.5 V limit (V_{DD_max}). Use equation (10) to determine the minimum capacitance value.

$$C_{VDD} = \frac{C_L V_{pk}^2}{V_{DD \text{ max}}^2 - V_{BUS \text{ max}}^2}$$
 (10)

When selecting the capacitor, make sure to select a capacitor with an effective capacitance close to the capacitance value determined by equation (10).

7.6 Design Methodology: programming

Many operational settings are adjustable through the digital front end. One should program the following parameters according to its specific design. For details, see section 7.5.

7.6.1 Waveform Playback

The readout rate for waveform playback is set using the following parameter:

Set FIFO readout speed using <u>PLAY_SRATE[2:0]</u> bits.

7.6.2 Power Converter

The internal buck-boost converter can be optimized using the following parameters:

- Set the maximum switching frequency of the power converter using FSWMAX[1:0] bits.
- Set the Power Input mode using UPI bits.



7.6.3 Loop Controller

The BOS1921/BOS1931 implements a proportional-integral (PI) control loop feedback that can be optimized if required with the following parameters:

- Proportional gain is set using KP[10:0]
- Proportional gain term related to waveform amplitude is used with <u>KPA[7:0]</u>
- Integral term is set with <u>KIBASE[3:0]</u>

Table 50 shows the recommended value for a 100 nF load operating at up to 190 V_{pk-pk} at 300 Hz with $L_1 = 10 \mu H$ and $R_{sense} = 0.2 \Omega$ sense resistor.

Table 50: Loop controller parameters

PARAMETER	RECOMMENDED VALUE	COMMENT
KP[10:0]	128 (0x080), default	Reduce value for smaller loads
KPA[7:0]	160 (0xA0), default	Reduce value for smaller loads
KIBASE[3:0]	2 (0x2), default	Increase value up to 4 when using a larger inductor

7.6.4 Power Efficiency

The power efficiency of the BOS1921/BOS1931 and the haptic waveform integrity can be optimized by configuring the internal controller and the switching timing of the internal low-side and high-side switches. This optimization can be done by adjusting the following registers based on selected inductor value (L_1) and current sense limit (set by R_{sense}):

- Optimize Loop Controller (see section 7.6.3).
- Adjust power switch deadtime using DHS[6:0] and DLS[6:0] bits.
- Adjust minimum current required to turn-on HS using IONSCALE[7:0] bits.
- Adjust typical capacitance value on pin SW using PARCAP[7:0] bits.
- Adjust proportional gain for the offset using <u>TI_RISE[5:0]</u> bits.
 Set the nominal supply voltage (VDD) of the design using <u>VDD[4:0]</u> bits.



7.7 Noise Reduction

It may be required to enable continuous conduction mode (CCM) by setting the $\underline{\text{CCM}}$ bit to 0x1 to drive a high capacitance load at high frequencies. In such a situation, the noise level on the supply nodes (i.e., V_{DDIO} , V_{BUS} and V_{DD}) may be higher than what is acceptable for some applications. Electrical noise can be reduced by using one or multiple of the following strategies:

- 1. Follow the PCB layout recommendations listed in the section 8.
- 2. Place a Schottky diode as close as possible to the BOS1921/BOS1931 device with a low threshold voltage and fast recovery time in the following locations:
 - a. Between the HV and SW pins, as shown in Figure 39.
 - b. Between the SW and PGND pins, as shown in Figure 39.

In the case where only one diode can be used due to cost or space, the Schottky diode between the HV and SW pins will generally have a more significant impact on noise reduction and should be prioritized rather than the diode placed between SW and PGND.

3. Decrease the maximum switching frequency of the BOS1921/BOS1931 by increasing FSWMAX[2:0] to up to 0x3 to increase the input power threshold for entering CCM mode.

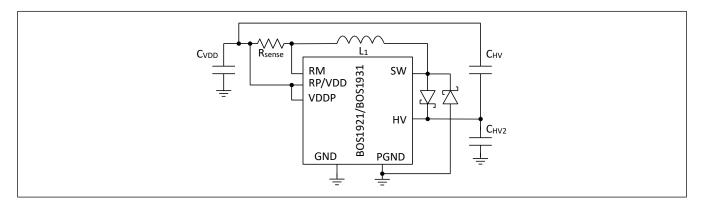


Figure 39: Simplified schematic with a Schottky diode between SW/HV and SW/PGND pins for noise reduction



8 PCB Layout Example

UPI configuration 4-layer PCB layout examples are presented in Figure 40. The recommended layers are as following:

- Top layer: Components and main routing.
- Layer 2: Full ground plane, avoid interruptions/slot as much as possible.
- Layer 3: Power plane split between V_{BUS}, V_{DD} and V_{DDIO}.
- Bottom layer: Routing.

Layout considerations:

- 1. Keep SW node as small as possible.
- 2. Place and route components L_1 , R_S , C_{VDD} , C_{HV} and C_{HV2} close to each other to minimize area of the high di/dt current loop and reduce high voltage ringing & spikes.
- 3. Create a GND island on Top layer connecting GND pads of C_{VDD} and C_{HV2} with the following criteria:
 - Connect this copper region to PGND pads of BOS1921/BOS1931.
 - Connect with vias to Layer 2 ground plane.
 - This GND island must not be tied to the Top layer ground polygon/plane (if applicable).
- 4. Route RP/VDD & RM sensing lines parallel to each other.
- 5. Create a HV copper region on Top layer connecting VDD pads of C_{HV} and C_{HV2}.
 - Connect this copper region directly to HV pad(s) of BOS1921/BOS1931.
 - Keep this region as close as possible to BOS1921/BOS1931.
 - Keep this region as small as possible.
- 6. This consideration applies to QFN version only Create a V_{DD} copper region on Top layer connecting VDD pad of C_{HV}:
 - Connect this copper region directly to VDDP pads (2 and 24 pins) of BOS1921/BOS1931.
 - Connect with vias to Layer 3 V_{DD} plane.

Notes on important components:

- The layout examples are sized for a piezo actuator with a capacitance of 100 nF driven at $190 \, V_{pk-pk}$ and $300 \, Hz$.
- Beware of capacitors DC bias, i.e., the decrease in capacitance with increasing DC voltage, which
 affects the effective value of a capacitor at a given operating voltage. Generally, high capacitance
 & high-voltage ceramic capacitors are subject to this phenomenon, but COG/NPO dielectric and
 tantalum capacitors do not exhibit any DC bias behavior. Refer to CHV2 and CVDD components in
 Table 51.
- Component requirements must be reevaluated for each application.



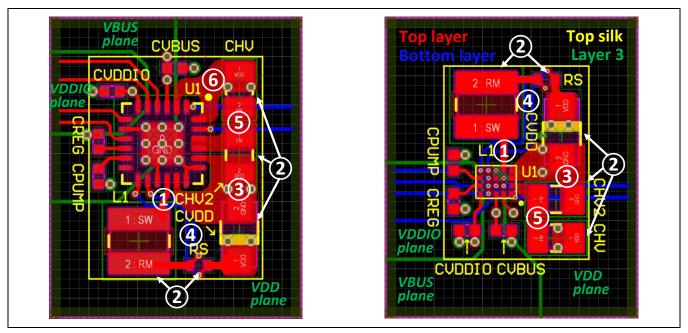


Figure 40: UPI configuration PCB layout examples for QFN 24L 4.0mm \times 4.0mm (left) and typical configuration for WLCSP 20B 2.1mm \times 1.7mm (right)

Table 51: Bill of Materials for layout examples

DESIGNATOR	QTY	VALUE	DESCRIPTION	MANUFACTURER	PART NUMBER	
CHV	1	0.01μF	10000PF 250V X7R 0805	TDK Corporation	CGA4J3X7R2E103K125AA	
CHV2	1	3900pF	3900PF 250V COG/NPO 0805	TDK Corporation	C2012C0G2E392J125AE	
CPUMP, CREG, CVBUS, CVDDIO	4	0.1μF	0.1UF 25V X5R 0402 Taiyo Yuden TMK105BJ1		TMK105BJ104KV-F	
CVDD	1	100μF	TANT POLY 100UF 6.3V 1206 KEMET T527I107		T527I107M006ATE070	
L1	1	10μΗ	IND 10UH 1.48A 415 MOHM TDK Corporation VLS301 3×3 mm package		VLS3012HBX-100M	
RS	1	0.2	0.2 OHM 1% 1/8W 0402	TE Connectivity Passive Product	RLP73N1ER20FTDF	



9 Mechanical

9.1 QFN Package Description

9.1.1 Physical Outline Dimension (POD)

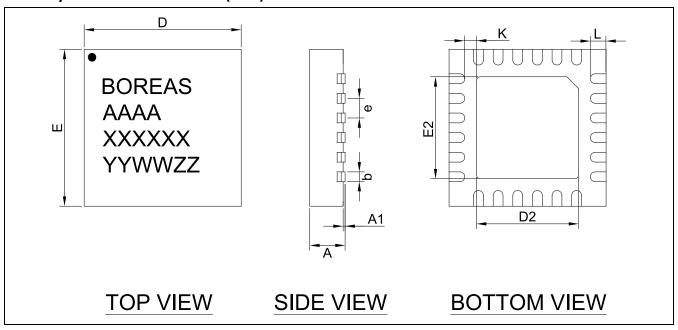


Figure 41: QFN 24L 4.0mm × 4.0mm package outline drawing

Table 52: QFN 24L 4.0mm × 4.0mm package dimensions

SYMBOL	MILLIMETERS					
	MIN	NOM	MAX			
Α	0.500	0.550	0.600			
A1	0.000	-	0.050			
b	0.200	0.250	0.300			
D	3.950	4.000	4.050			
D2	2.350	2.400	2.450			
E	3.950	4.000	4.050			
E2	2.350	2.400	2.450			
е	0.500 BSC					
К	0.325	0.400	0.475			
L	0.350	0.400	0.450			

[‡]Reference: JEDEC MO-220-WGGD. BSC: Basic Spacing between Center.

Four lines are branded on the package:

(1) Company Name: BOREAS

(2) Device Marking: AAAA (1921 or 1931)

(3) Wafer Batch Number: XXXXXX

(4) Assembly Date Code: YY (year), WW (week) and ZZ (assembly house code)



9.1.2 QFN Package Soldering Footprint

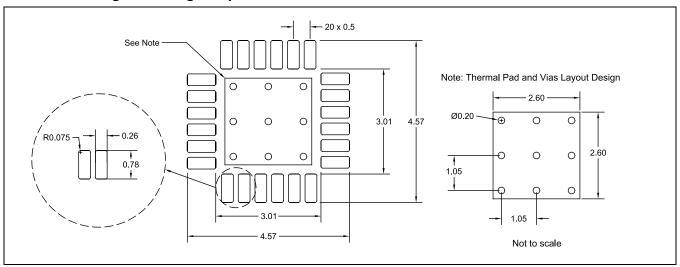


Figure 42: QFN 24L 4.0mm × 4.0mm soldering footprint (NOT TO SCALE)

9.1.3 QFN Reflow

The QFN package soldering reflow profile should be determined based on the recommended reflow profile made by the manufacturer of the solder paste used. Also, it is important to take into consideration that the circuit board dimensions, other board components and the reflow soldering oven may affect the reflow profile.

Finally, please note that the quality of the solder paste plays an important role in board assembly and allows for a reliable and repeatable assembly process.



9.2 WLCSP Package Description

9.2.1 Physical Outline Dimension (POD)

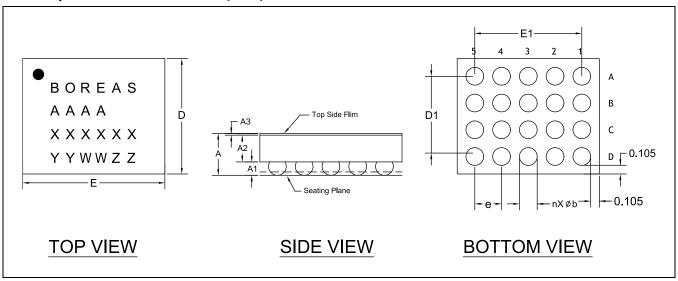


Figure 43: WLCSP 20B 2.1mm × 1.7mm package outline drawing with top, side, and bottom view

Table 53: WLCSP 20B 2.1mm × 1.7mm package dimensions

SYMBOL	MILLIMETERS						
STIVIBUL	MIN	NOM	MAX				
Α	0.585	0.625	0.665				
A1	0.180	0.200	0.220				
A2	0.380	0.400	0.420				
A3	0.022	0.025	0.028				
Е	2.055	2.075	2.095				
D	1.655	1.655 1.675 1.695					
E1	1.60 BSC						
D1	1.20 BSC						
е	0.40 BSC						
b	0.245 0.265 0.285						

BSC: Basic Spacing between Center.

Four lines are branded on the package:

(1) Company Name: BOREAS

(2) Device Marking: AAAA (1921 or 1931)

(3) Wafer Batch Number: XXXXXX

(4) Assembly Date Code: YY (year), WW (week) and ZZ (assembly house code)



9.2.2 WLCSP Package Soldering Footprint

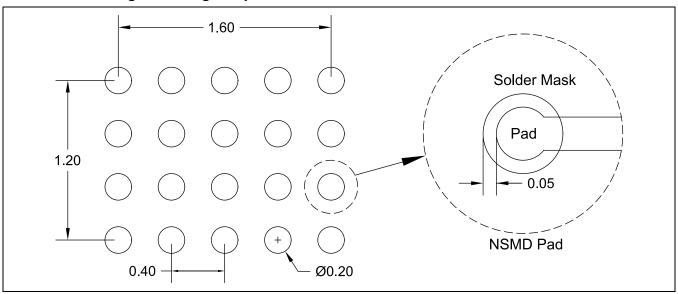


Figure 44: WLCSP 20B 2.1mm × 1.7mm soldering footprint (NOT TO SCALE)

The use of non-solder mask defined (NSMD) pads is recommended, with 0.05 mm solder mask expansion as shown in Figure 44.



9.2.3 WLCSP Reflow

BOS1921CW have SAC405 bumps which supports JEDEC J-STD-020D.1 reflow profile. Figure 45 presents the recommended reflow profile which may be optimized for specific PCB assembly conditions. Note that it is recommended to use solder paste to obtain reliable solders.

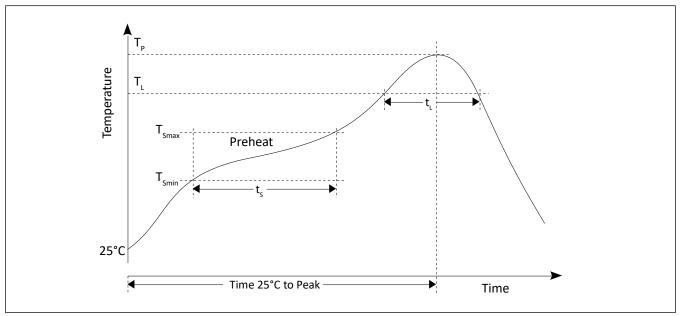


Figure 45: WLCSP reflow profile

Table 54: Reflow profile parameters

PARAMETER	DESCRIPTION	VALUE
T _{Smin}	Preheat minimum temperature	150°C
T _{Smax}	Preheat maximum temperature	200°C
ts	Time from T _{Smin} to T _{Smax}	60-120 s
	Ramp-up rate from T _L to T _P	3°C/s max
TL	Liquidous temperature 217°C	
ТР	Peak package temperature 260°C	
t∟	Time above T _L	60-150 s
	Ramp-down rate from T _P to T _L	6°C/s max
	Time 25 °C to peak temperature	8 min max



9.3 Tape and Reel Specifications

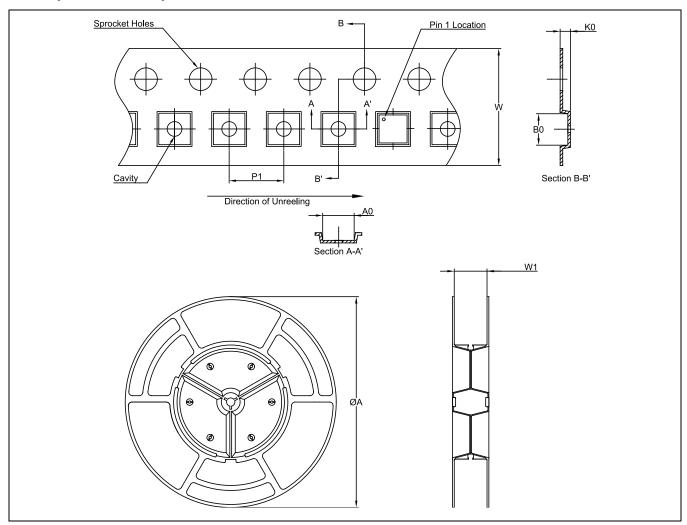


Figure 46: Embossed carrier tape and reel outline drawing

Table 55: Tape and reel dimensions

PART NUMBER	PACKAGE TYPE	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W	ØA (mm)	W1 (mm)
BOS1921CQ	QFN 24L 4.0mm × 4.0mm	4.250	4.250	0.750	8.00	12.00	330	12.4
BOS1931CQ	QFN 24L 4.0mm × 4.0mm	4.250	4.250	0.750	8.00	12.00	330	12.4
BOS1921CW	WLCSP 20B 2.1mm × 1.7mm	2.275	1.875	0.825	4.00	8.00	178	9
BOS1931CW	WLCSP 20B 2.1mm × 1.7mm	2.275	1.875	0.825	4.00	8.00	178	9



10 Known Issues

10.1 Incorrect Activation of Output Bridge Protection

Affected product revision: B

The output bridge protection (section 6.2.18) is activated under the following conditions:

- Play a positive haptic waveform when a negative voltage smaller than -2.5 V has built up on the piezoelectric ceramic.
- Play a negative haptic waveform when a positive voltage greater than 2.5 V has built up on the piezoelectric ceramic.

In these conditions, the device may output the waveform with the wrong polarity and generate an IDAC fault.

To avoid this issue, one must reset the voltage on the piezoelectric ceramic before starting to play the haptic waveform. This can be achieved by playing one of the following sets of data before the desired haptic waveform:

- Several 0 V data points.
- Voltage data points increasing from -2 V to 0 V if a positive waveform is intended to be played.
- Voltage data points decreasing from 2 V to 0 V if a negative waveform is intended to be played.

10.2 Timeout resets PLAY_SRATE

Affected product revision: All

When using the timeout feature with the <u>TOUT</u> bit set to 0x1, the <u>PLAY_SRATE[2:0]</u> bits are reset to 0x7 when the device enters SLEEP after a timeout event.

10.3 Waveform Amplitude Drift with RELOFF Option

Affected product revision: All

When using RAM Synthesis mode with the <u>RELOFF</u> option enabled, an offset may cumulate when 2 SLICEs of different amplitudes are repeatedly played. This cumulative offset can cause waveform amplitude to drift, potentially leading the device to enter an ERROR state.

To prevent this waveform amplitude drift, avoid repeating SLICE with different amplitudes while using the <u>RELOFF</u> option, ensure that each SLICE has identical amplitude or reduce the number of times the SLICEs are repeated.

10.4 Minimum Slew-Rate of V_{BUS} Supply

Affected product revision: A, B & C

The V_{BUS} voltage must ramp-up at a minimum rate of 3 V/ms to ensure proper device initialisation.



11 Ordering Information

Table 56: Ordering information

ORDERING PART NUMBER	FEATURES	PACKAGE DESCRIPTION	PACKING FORMAT	QUANTITY	MSL LEVEL, PEAK TEMP.	FLOOR LIFE	OPERATING TEMPERATURE	DEVICE MARKING
BOS1921CQR	DRIVE+SENSE	QFN 24L 4.0mm × 4.0mm	Tape & Reel	2500 / Reel	Level 3, 260°C	168Hrs	-40°C to 85°C	1921
BOS1931CQR	DRIVE	QFN 24L 4.0mm × 4.0mm	Tape & Reel	2500 / Reel	Level 3, 260°C	168Hrs	-40°C to 85°C	1931
BOS1921CWR	DRIVE+SENSE	WLCSP 20B 2.1mm × 1.7mm	Tape & Reel	4000 / Reel	Level 1, 260°C	Unlimited	-40°C to 85°C	1921
BOS1931CWR	DRIVE	WLCSP 20B 2.1mm × 1.7mm	Tape & Reel	4000 / Reel	Level 1, 260°C	Unlimited	-40°C to 85°C	1931

NOTE

- (1) Ordering Part Number where last letter indicates packing format.
- (2) All parts are RoHS compliant and halogen free.
- (3) Contact sales@boreas.ca to order.
- (4) MSL: Moisture Sensitivity Levels, IPC/JEDEC J-STD-020.



12 Document History

Table 57: Document changes between previous and current versions

ISSUE	DATE	DOCUMENT NUMBER	CHANGES
6	Oct., 2024	BT015DDS01.01	Added BOS1931 device Added I _{BUS,AVG} in sensing (section 5.4) Typo corrected (section 6.2.11) Changed minimum V _{BUS} ramp-up rate (section 7.4.1) Changed known issue name (section 10.1) Added known issue Waveform Amplitude Drift with RELOFF Option (section 10.3) Added known issue Minimum Slew Rate of VBUS Supply (section 10.4) Updated ordering information (section 11) Added C _{HV2} to Figure 35 Corrected wheel width for BOS1921CW (Table 55)
5	April, 2024	BT015CDS01.01	Added a note about Device Reset feature (section 6.2.8) Clarified the Adjustable Internal Clock (section 6.2.14) Updated Current Detection Status Fault description (section 6.2.15.5) Clarified interrupt mechanism (section 6.2.17) Added Output Bridge protection description (section 6.2.18) Updated digital interface terminology (section 6.3) Corrected FIFO descriptions (section 6.6) Clarified SLICE.AMPITUDE[11:0] definition (section 6.8.1) Clarified FSWMAX[1:0] field description (section 6.10.2) Added CHIP_REV[3:0] register field (section 6.10.17) Changed power-up sequence for VDDIO (section 7.4.1) Added guidelines for noise reduction (section 7.7) Modified layout recommendations (section 8) Changed known issue name IDAC fault bit (section 10.1) Added issue Timeout resets PLAY_SRATE (section 10.2) Corrected RAM Playback example (Figure 21) Corrected examples in Table 20



13 Notice and Warning

Warning High Voltage



For safety, this integrated circuit must be used by qualified and skilled personnel familiar with all applicable safety standards.

ESD Caution



This integrated circuit is ESD (Electrostatic Discharge) sensitive. Therefore, proper ESD precautions and procedures are recommended for handling and installation to avoid damage.

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